

2371-8

**Advanced Workshop on Energy Transport in Low-Dimensional Systems:
Achievements and Mysteries**

15 - 24 October 2012

Nanoscale Thermal and Thermoelectric Characterization Techniques

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Nanoscale Thermal and Thermoelectric Characterization Techniques

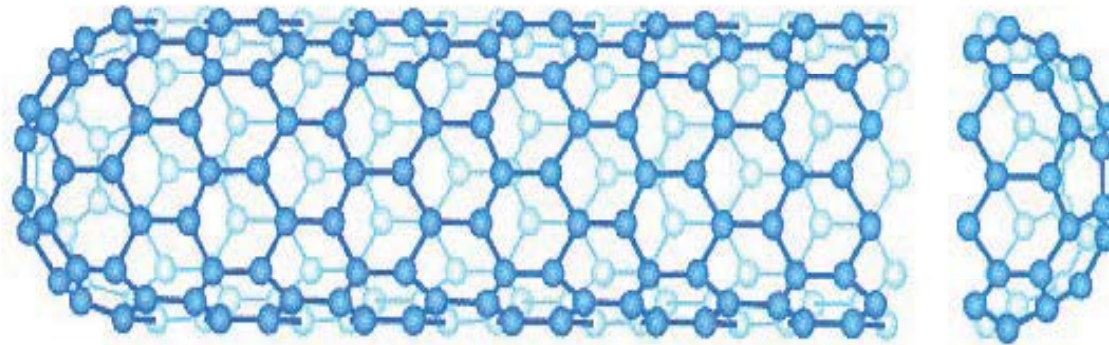
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shakouri@purdue.edu

Advanced Workshop on Energy Transport
in Low Dimensional Systems
15 October 2012



Thermal Transport in Low Dimension



Hot



Cold

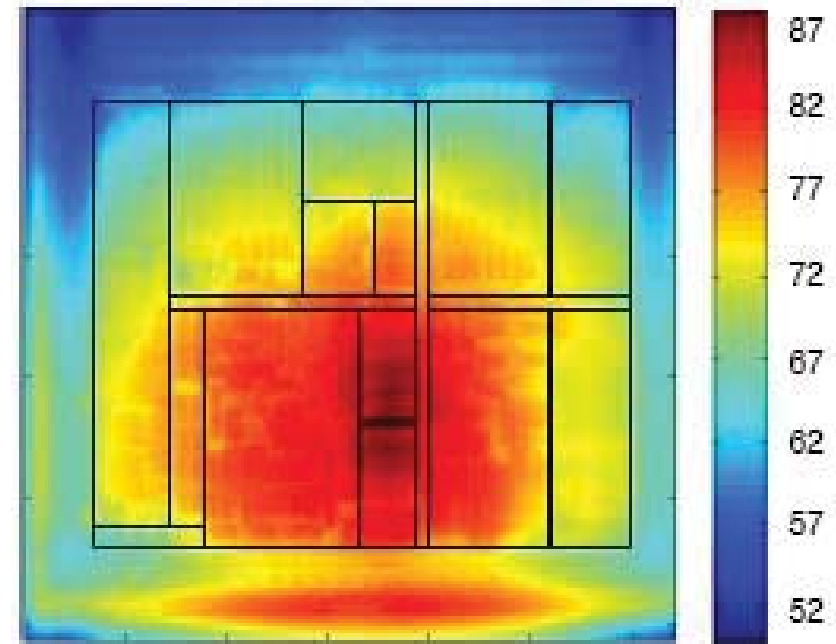
Thermal conductivity value?

Deviations from Fourier?



Non uniform temperature in CPUs (central processing units)

- Leakage power exponential increase with temperature
 - Potential thermal runaway
- Lifetime exponential decrease with temperature
 - ($\Delta T = 15C \rightarrow \frac{1}{4}$ lifetime)



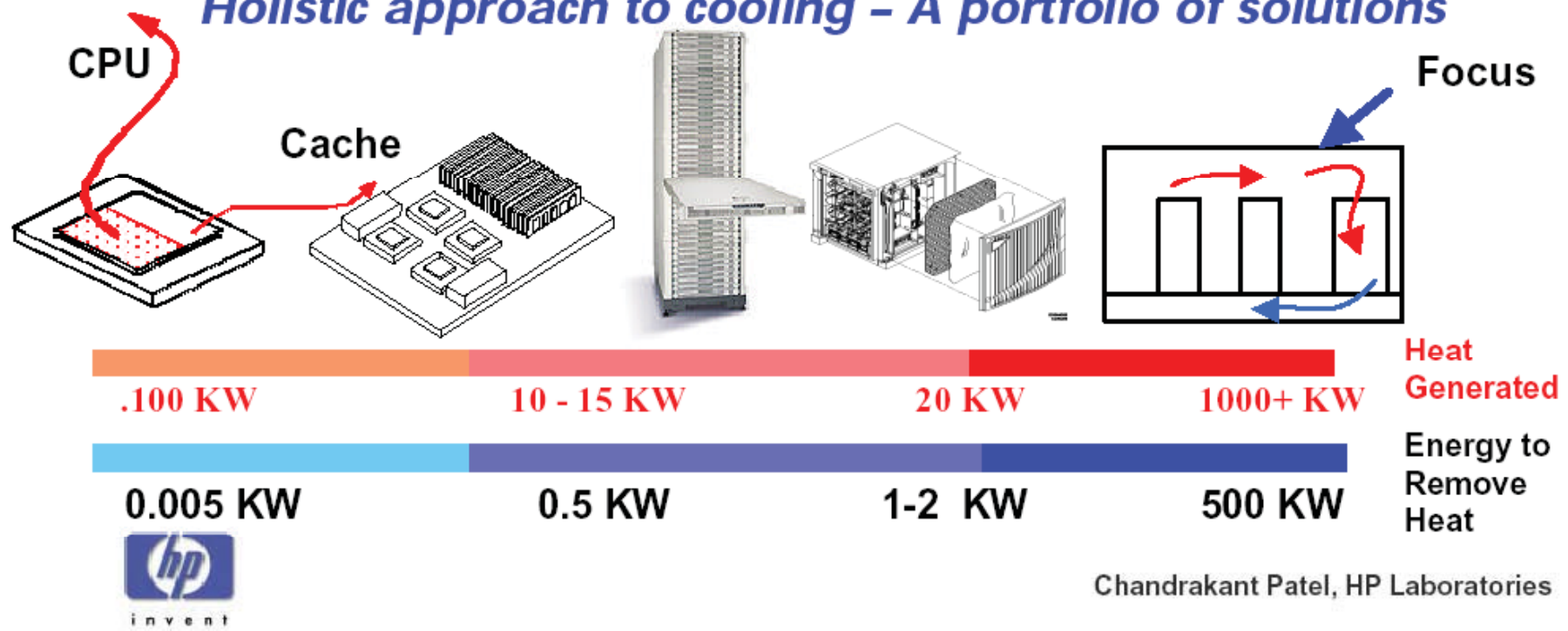
Measuring Power and Temperature from Real Processors, Javi Martinez, Jose Renau, et al. *The Next Generation Software (NGS) Workshop (NGS08)*, April 2008

<http://masc.cse.ucsc.edu>

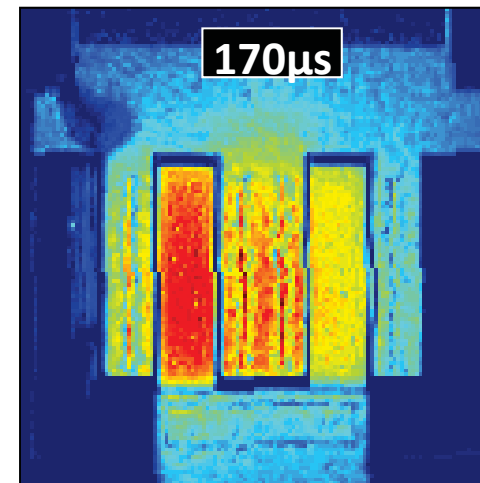
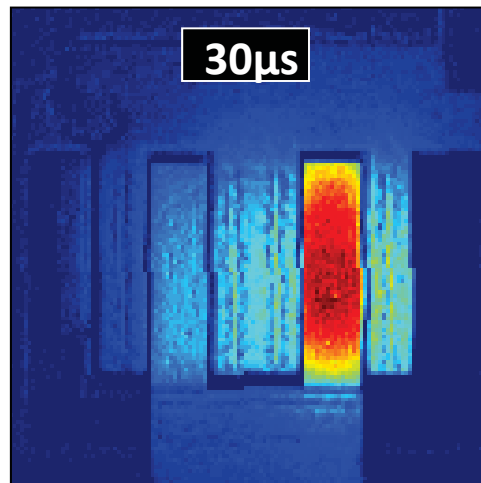
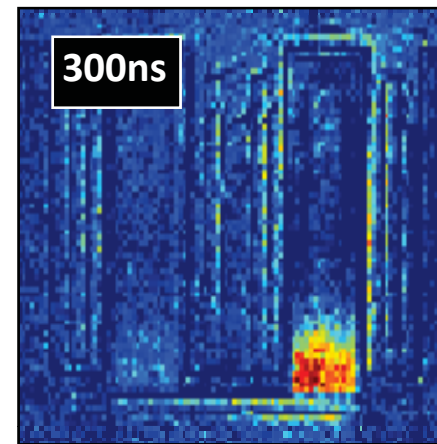
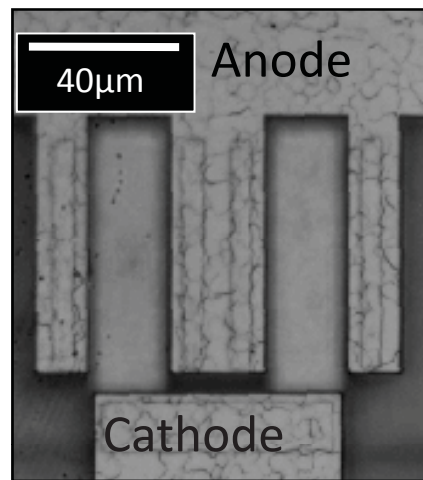


Power dissipation challenges

Holistic approach to cooling - A portfolio of solutions



Heating in Electro Static Discharge Devices

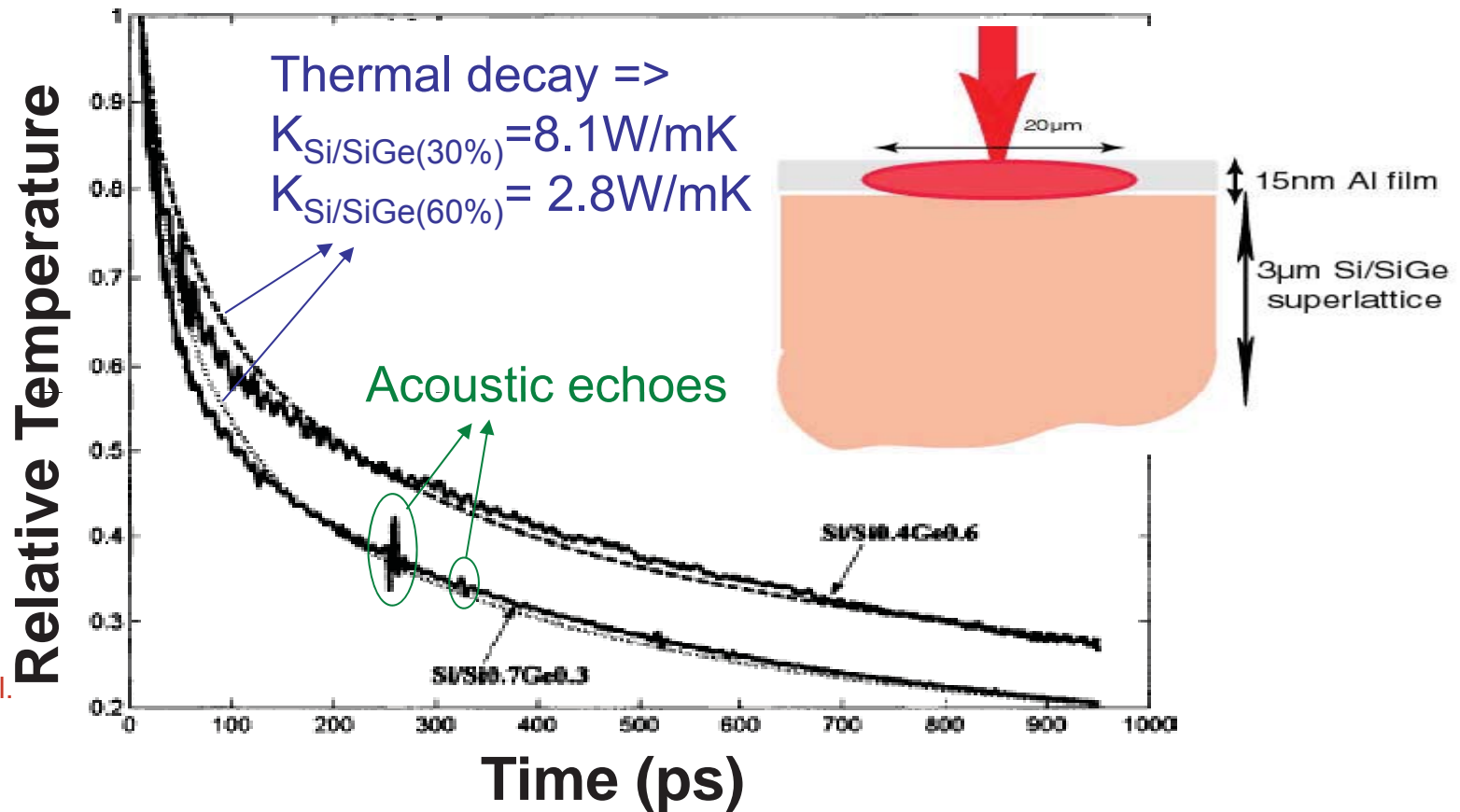


Snapback current = 1.22A.

K. Maize, V. Vashchenko et al, *IRPS*, 2011.



Thin Film Thermal Characterization



Y. Ezzahri et al. Appl.
Phys. Letters 2005

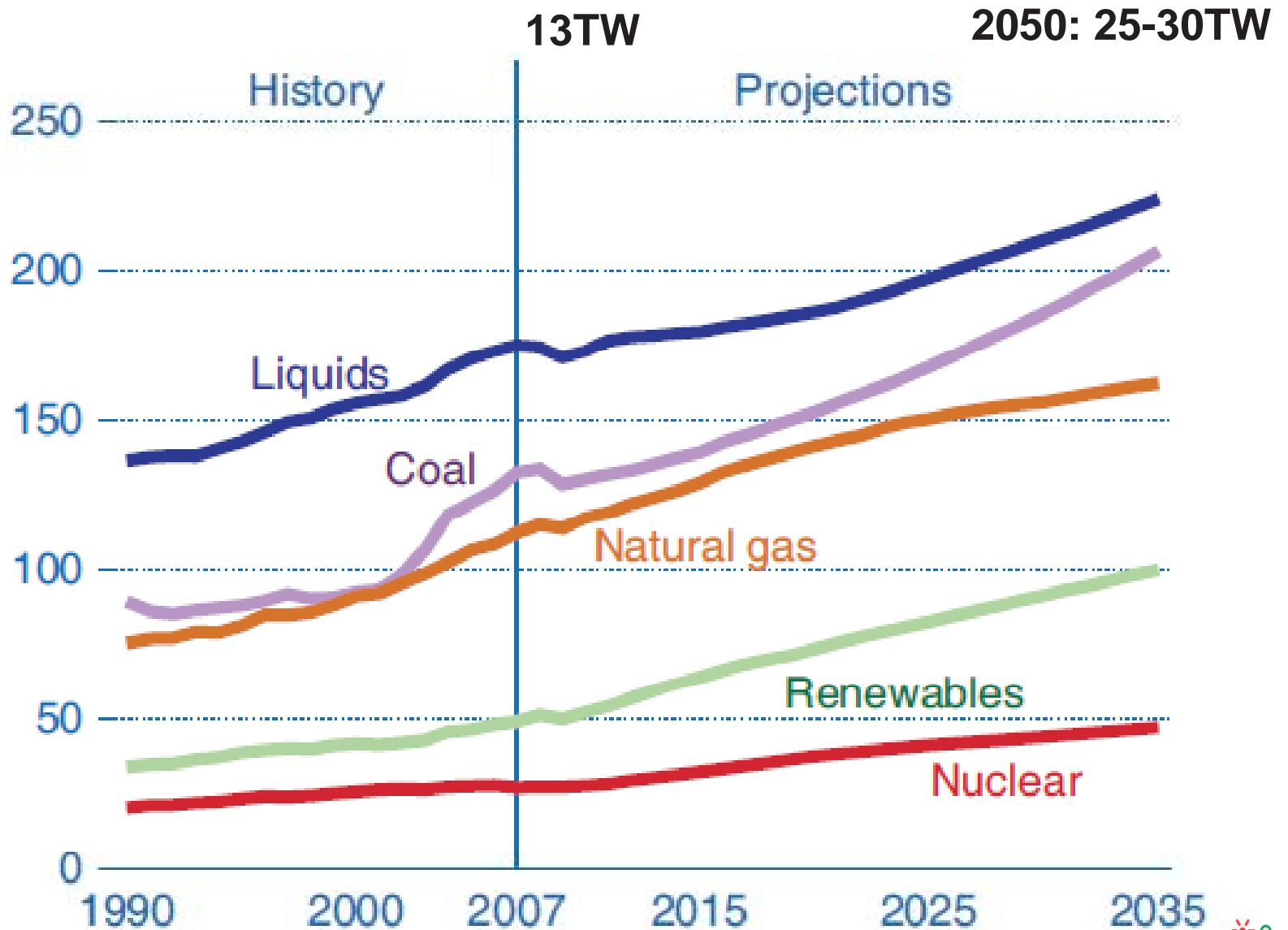
Metal film is heated by laser pulse and it acts as a **heat source**. It can characterize thermal interface resistances as well as thin film thermal conductivity.



World Marketed Energy Use 1990-2035

US Department of Energy; Energy Information Administration (2010)

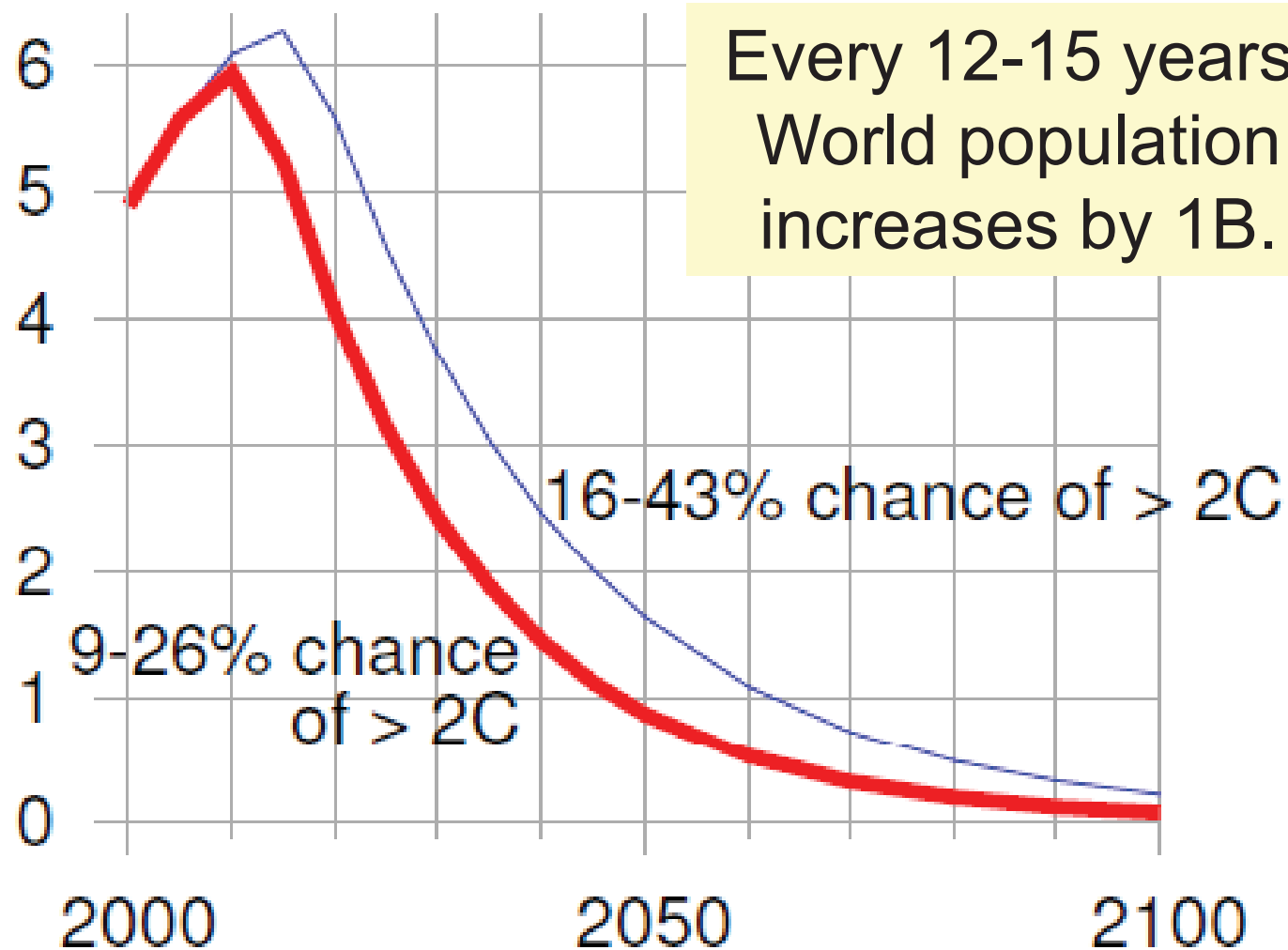
1 Quad = 1.055×10^{18} J
1 EJ = 31.7 GW



CO₂ Emission Goals (2000-2100)

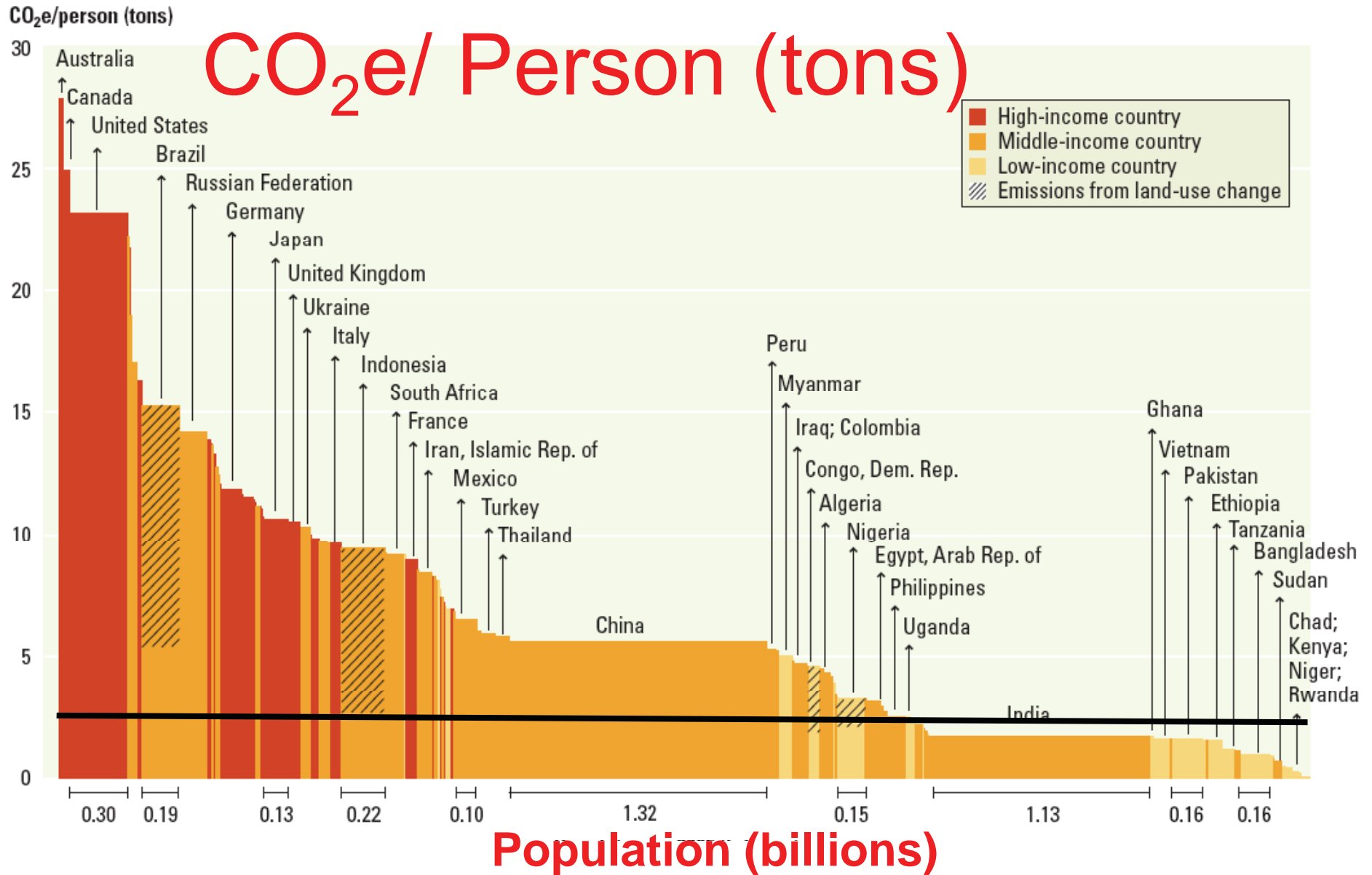
IPCC

tCO₂/y per person



David McKay, Sustainable Energy -Without the Hot Air

Figure 1.1 Individuals' emissions in high-income countries overwhelm those in developing countries



Sources: Emissions of greenhouse gases in 2005 from WRI 2008, augmented with land-use change emissions from Houghton 2009; population from World Bank 2009c.

Note: The width of each column depicts population and the height depicts per capita emissions, so the area represents total emissions. Per capita emissions of Qatar (55.5 tons of carbon dioxide equivalent per capita), UAE (38.8), and Bahrain (25.4)—greater than the height of the y-axis—are not shown. Among the larger countries, Brazil, Indonesia, the Democratic Republic of Congo, and Nigeria have low energy-related emissions but significant emissions from land-use change; therefore, the share from land-use change is indicated by the hatching.

- More than **90%** of primary energy is first converted to **heat**.
- Overall end-use **exergy** (12% of sources):
 - Motion 0.95 TW
 - Heat 0.73 TW
 - Cooling/Light/Sound 0.06 TW

Adapted from Cullen and Allwood, *Energy*, 2010

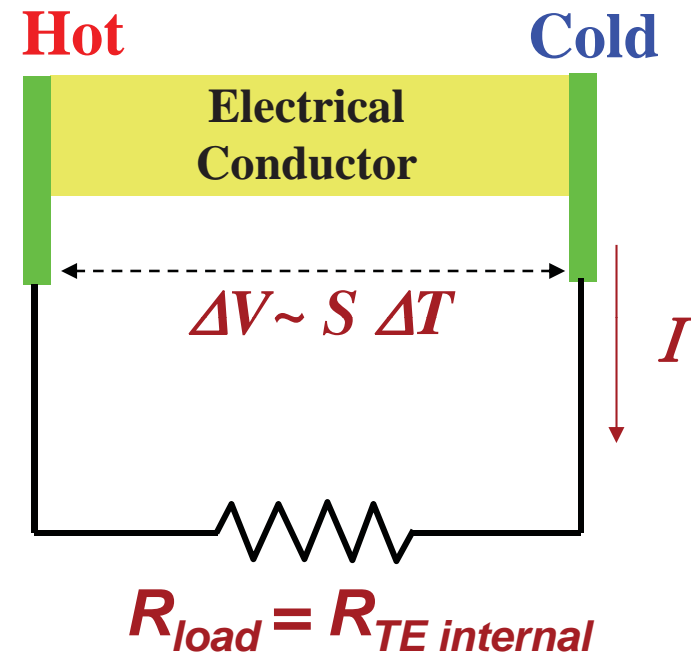


Seebeck coefficient
(1821) $S = \frac{\Delta V}{\Delta T}$

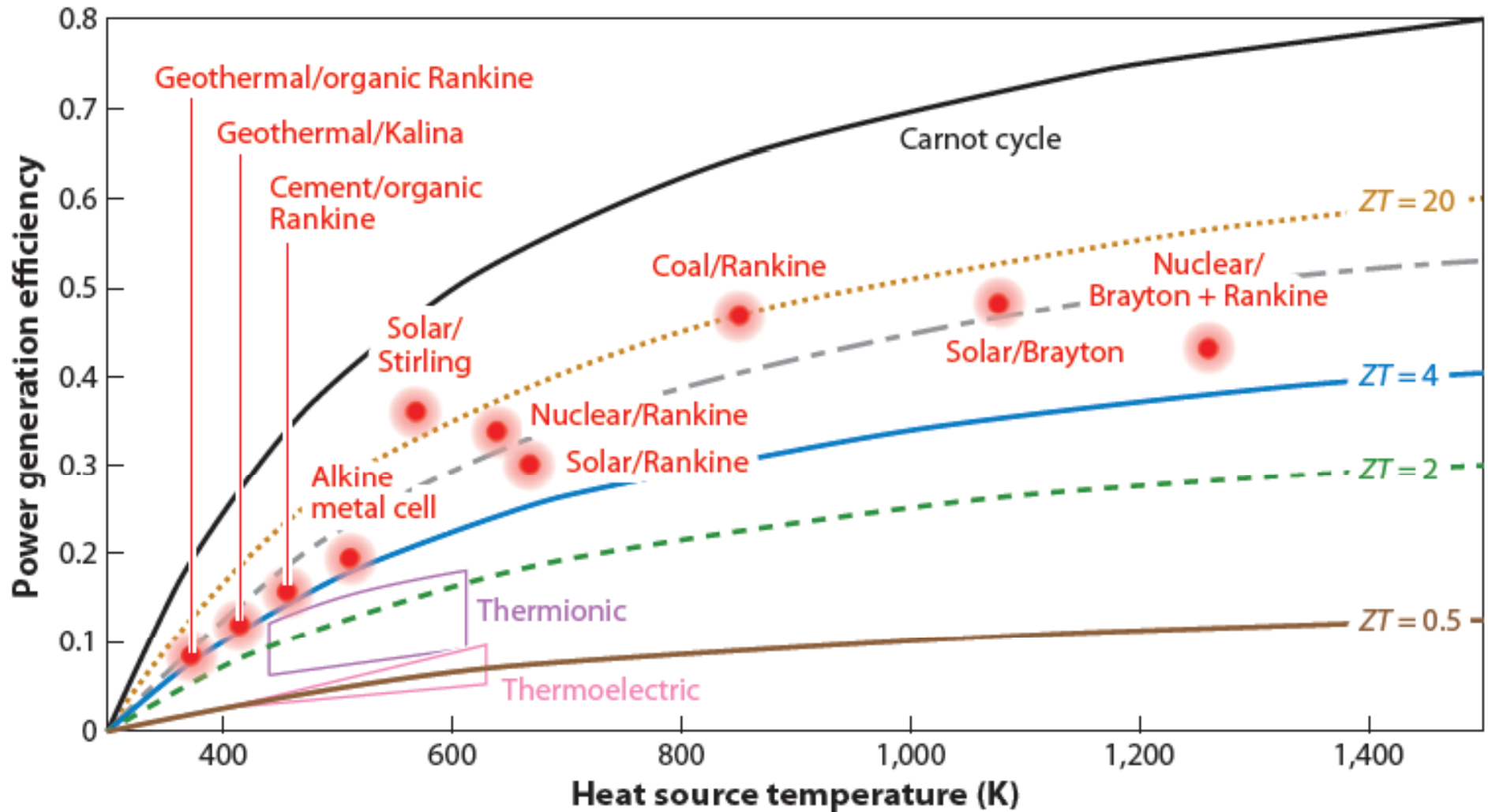
Efficiency function of
thermoelectric figure-of-merit (Z)

$$Z = \frac{S^2 \sigma}{k}$$

$$Z = \frac{(\text{Seebeck})^2 (\text{electrical conductivity})}{(\text{thermal conductivity})}$$



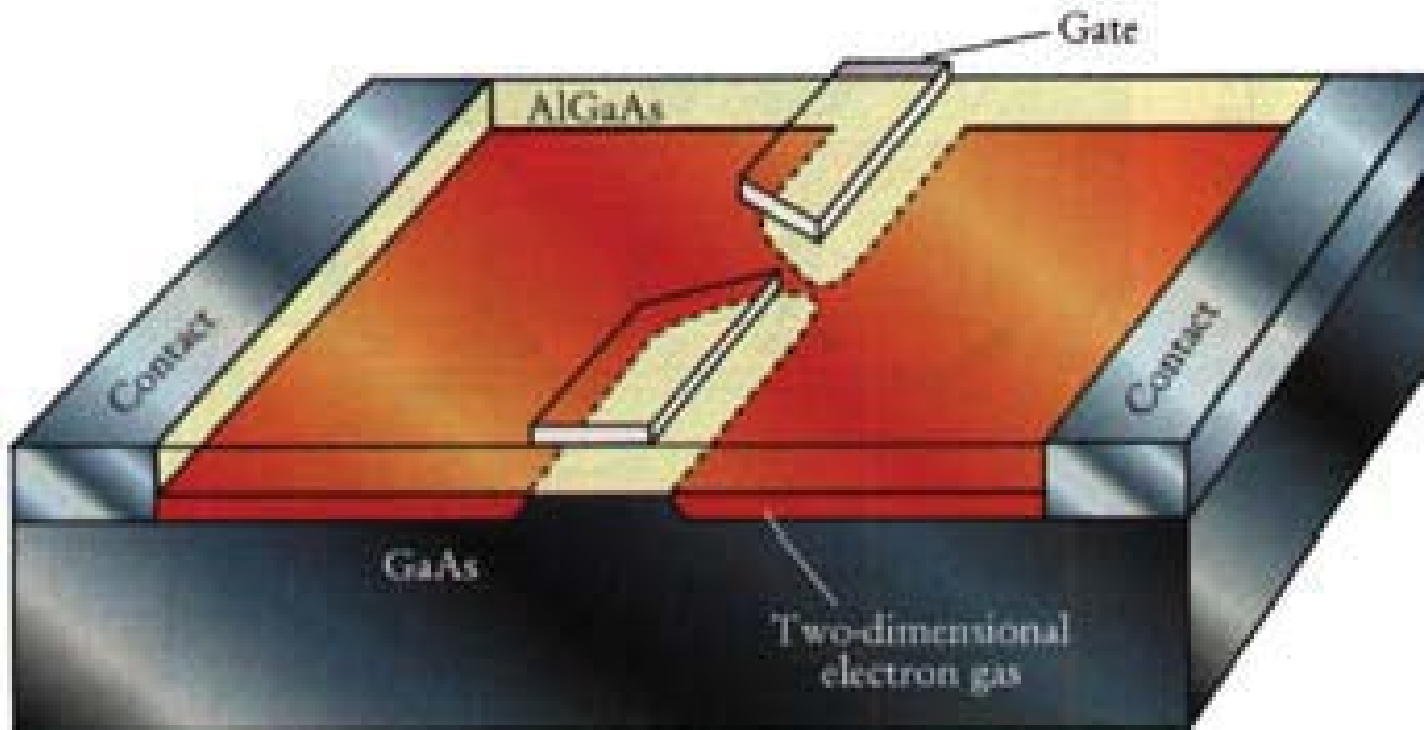
Power Generation Efficiencies



K. Yazawa and A. Shakouri, J. Appl. Phys. 111, 024509 (2012)
Adapted from Cronin Vining, Nature Materials 2009



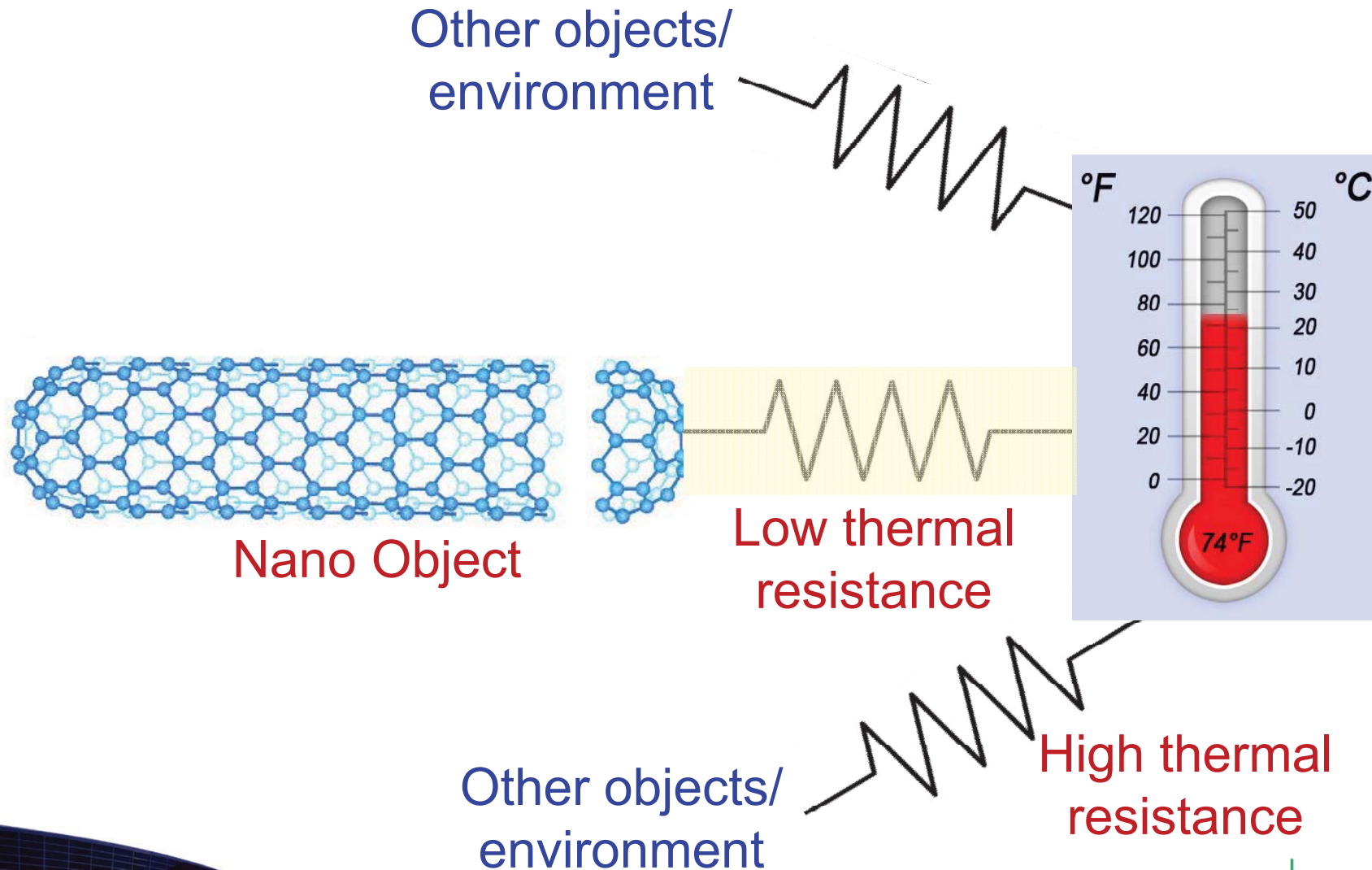
Measuring voltage at nanometer scale



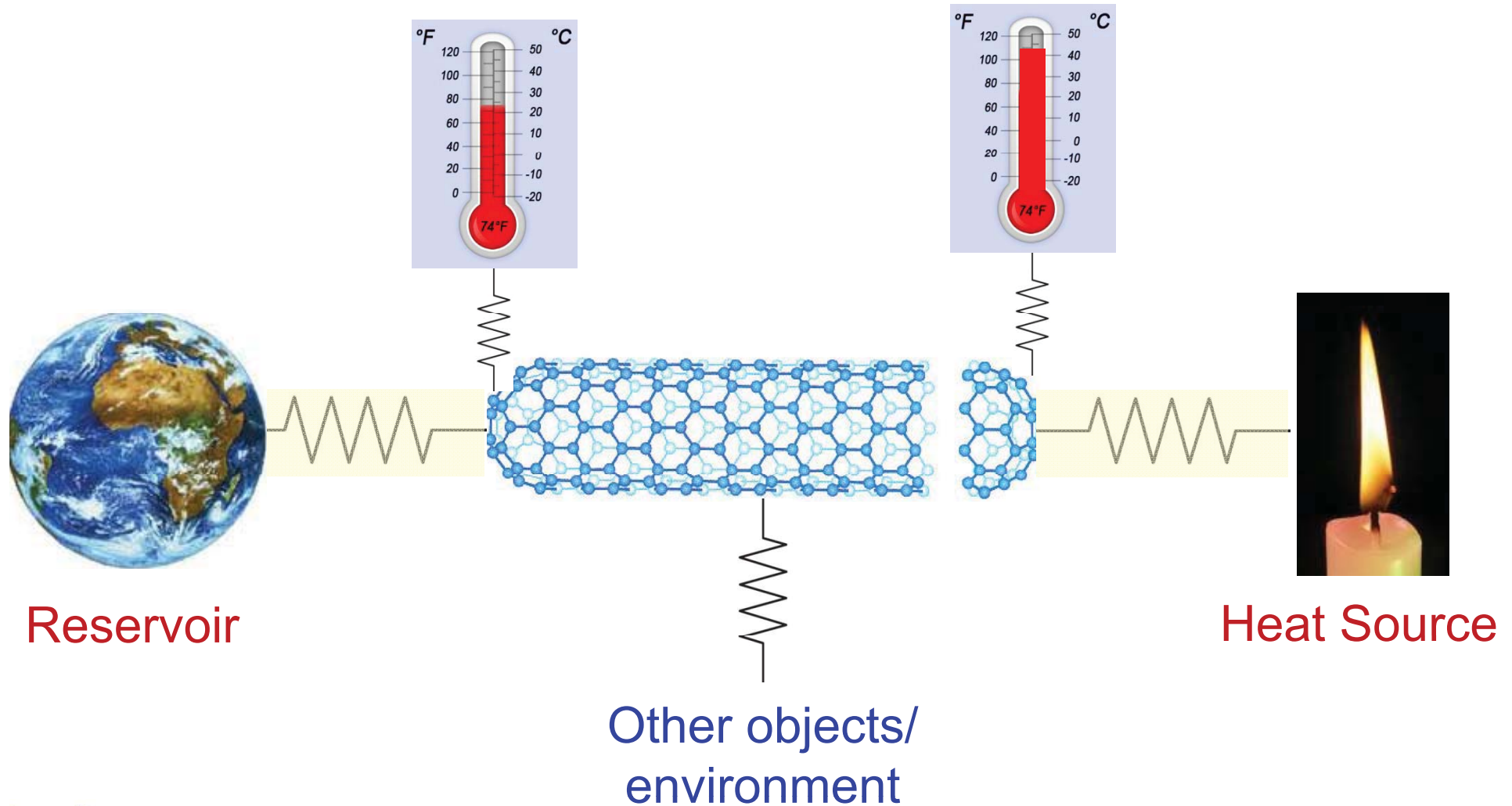
Quantum Point Contact



Measuring temperature at nanometer scale



Measuring heat flow at nanometer scale

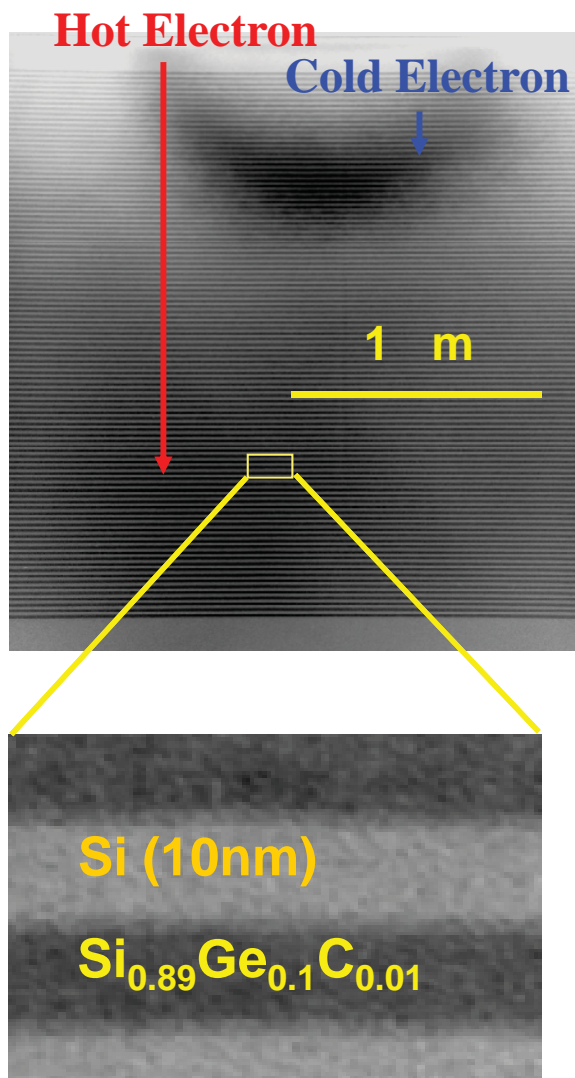


Classical thermal imaging techniques

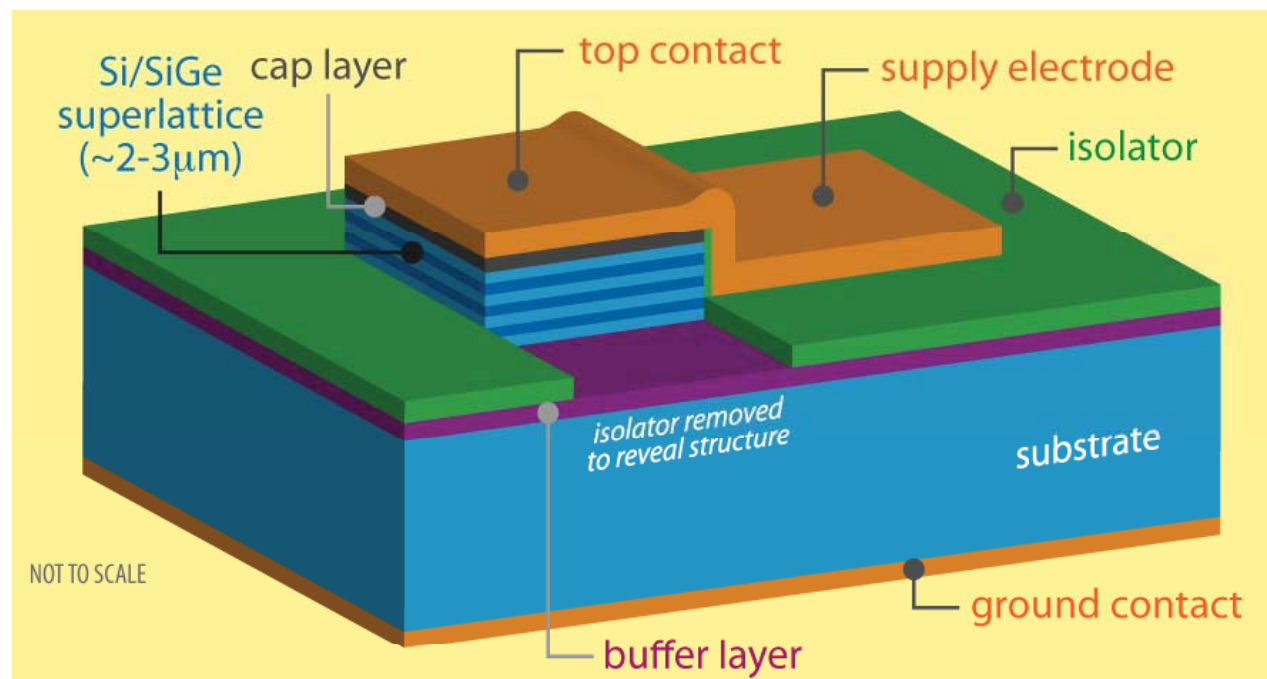
Method	Principle
Micro-thermocouple	Seebeck effect
Infrared Thermography	Planck blackbody emission
Liquid Crystal Thermography	Crystal phase transitions (change color)



Microrefrigerators on a chip



Implement selective emission of hot electrons (evaporative cooling) with heterostructure barriers.

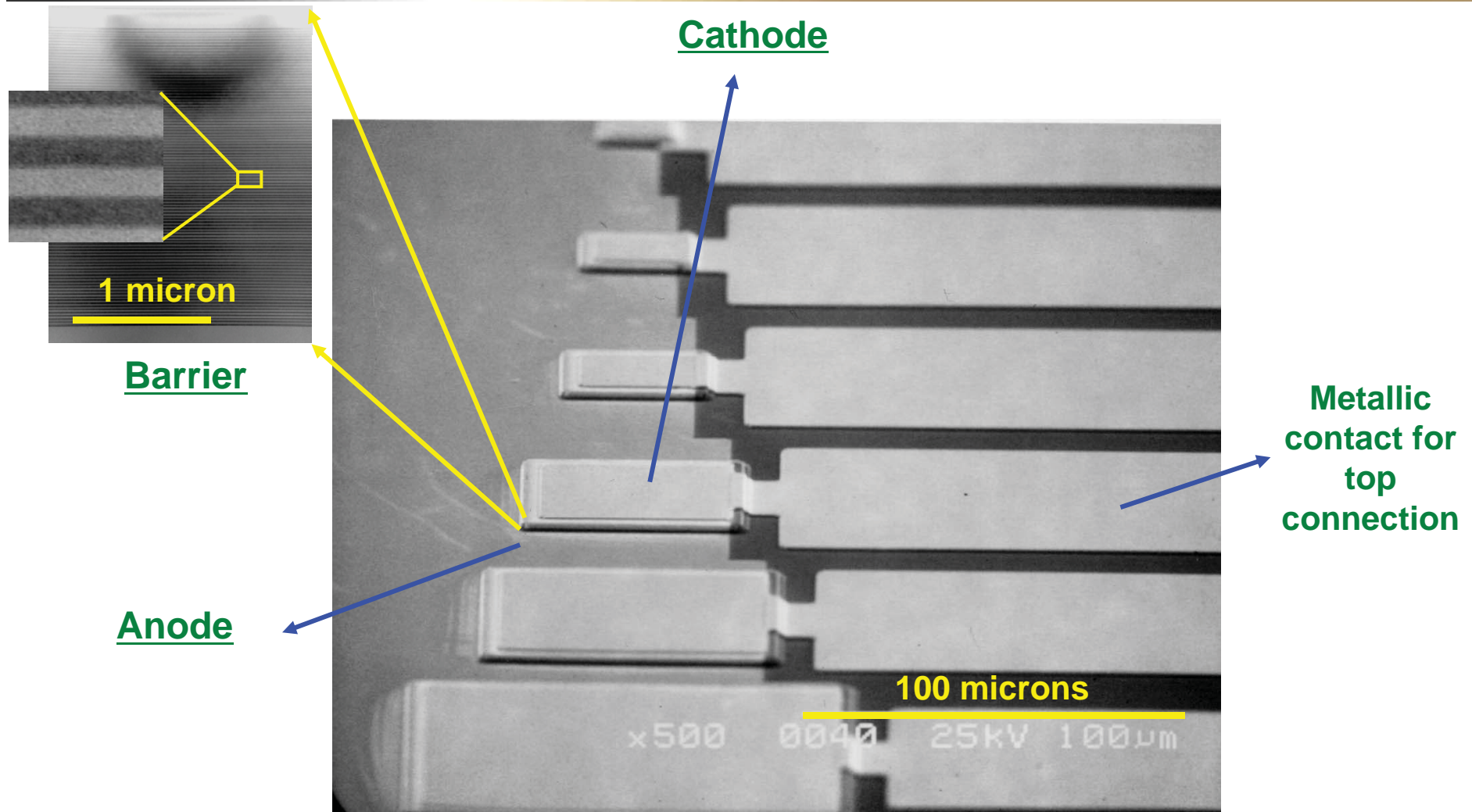


Heterostructure Integrated Thermionic Coolers; A. Shakouri and John Bowers, **Appl. Phys. Lett.** 1997

Nanoscale heat transport and microrefrigerators on a chip; A. Shakouri, **Proceedings of IEEE**, July 2006



Si/SiGe Micro refrigerator on a chip

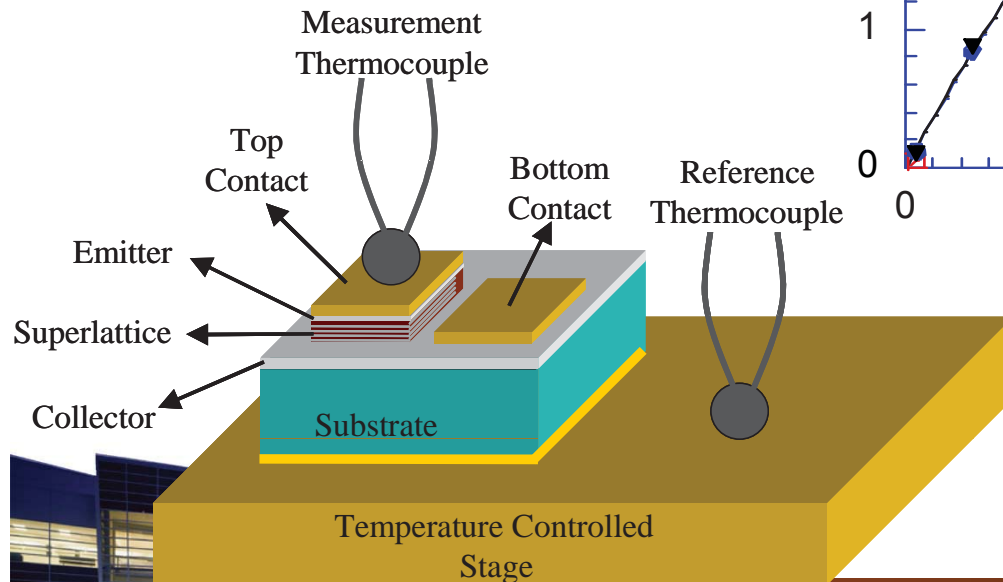
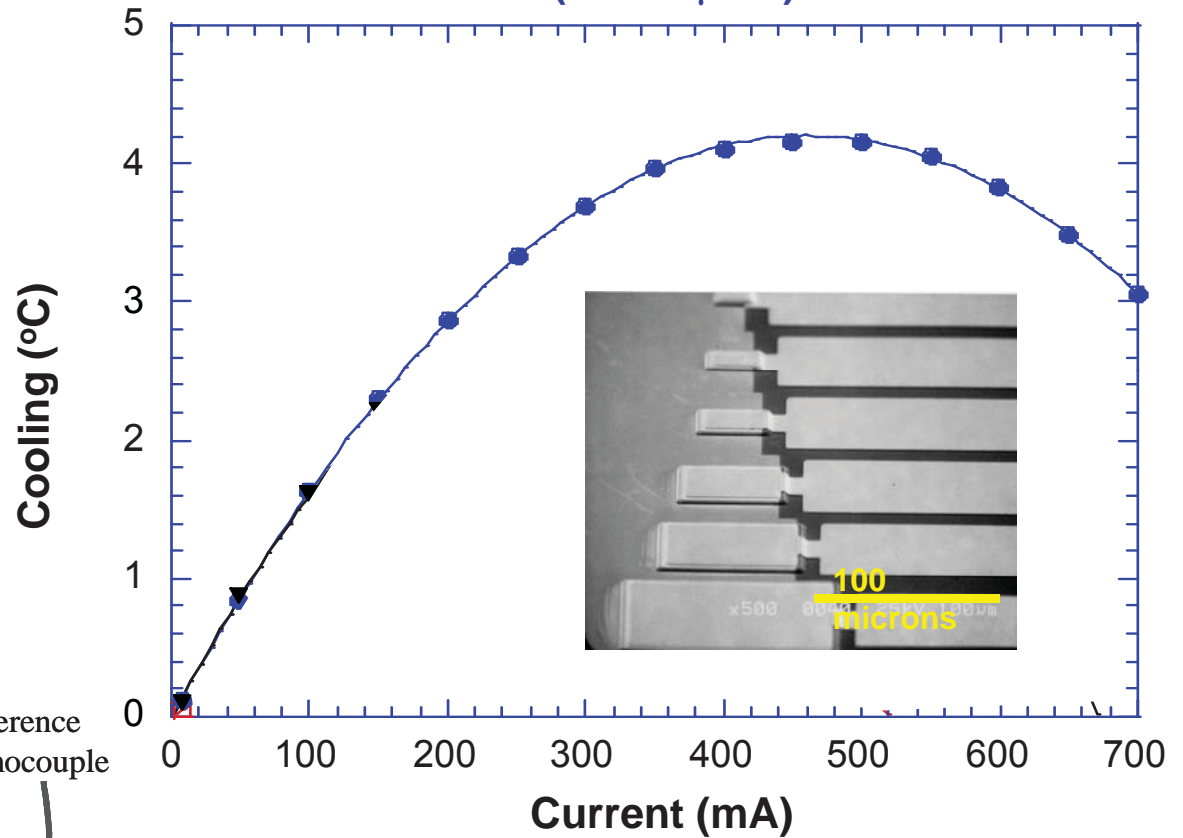


X. Fan, E.Croke, J.E. Bowers, A. Shakouri, et al.,
Applied Physics Lett. 78 (11), 2001.



Micro thermocouple measurements: Cooling vs. Current

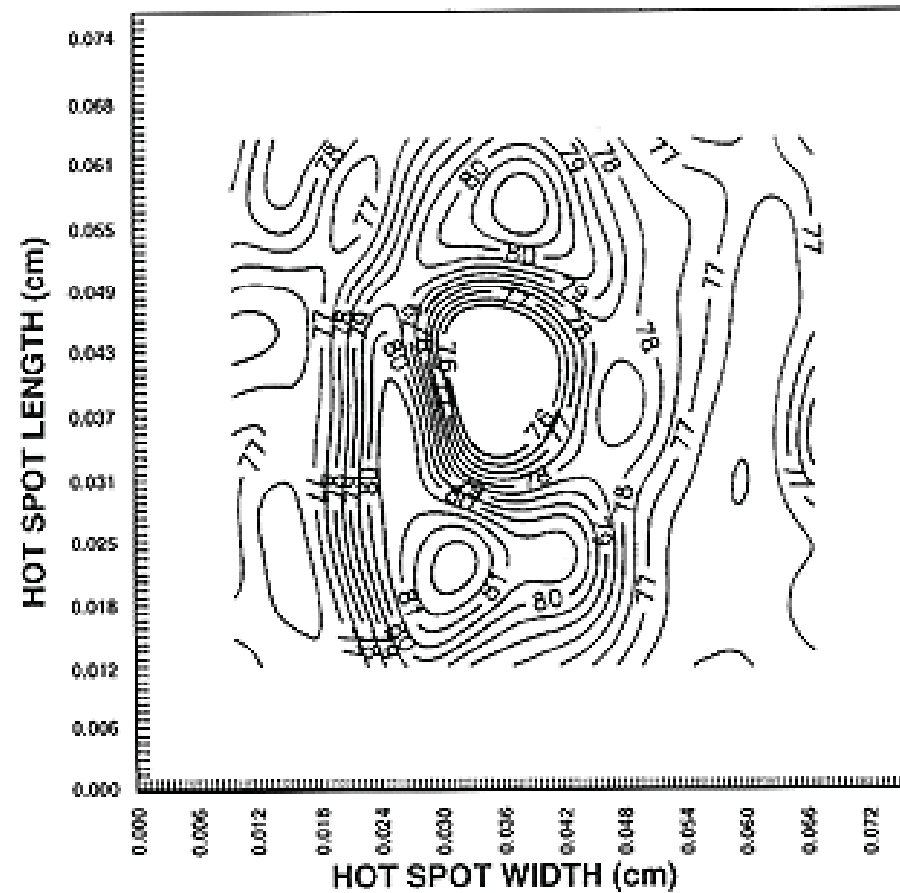
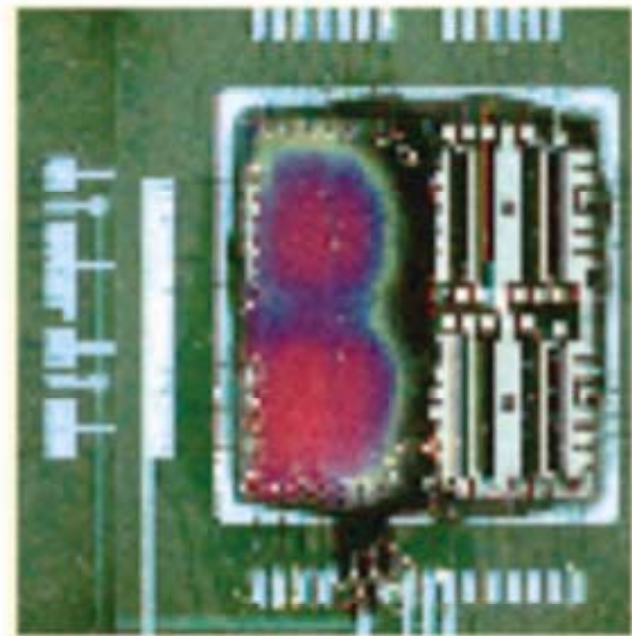
(60x60 μm^2)



X. Fan, E. Croke, A. Shakouri, J. E. Bowers, ...
"SiGe/Si Superlattice Coolers," Phys. Low-Dim.
 Struct., 5/6 (2000) pp. 1-10.

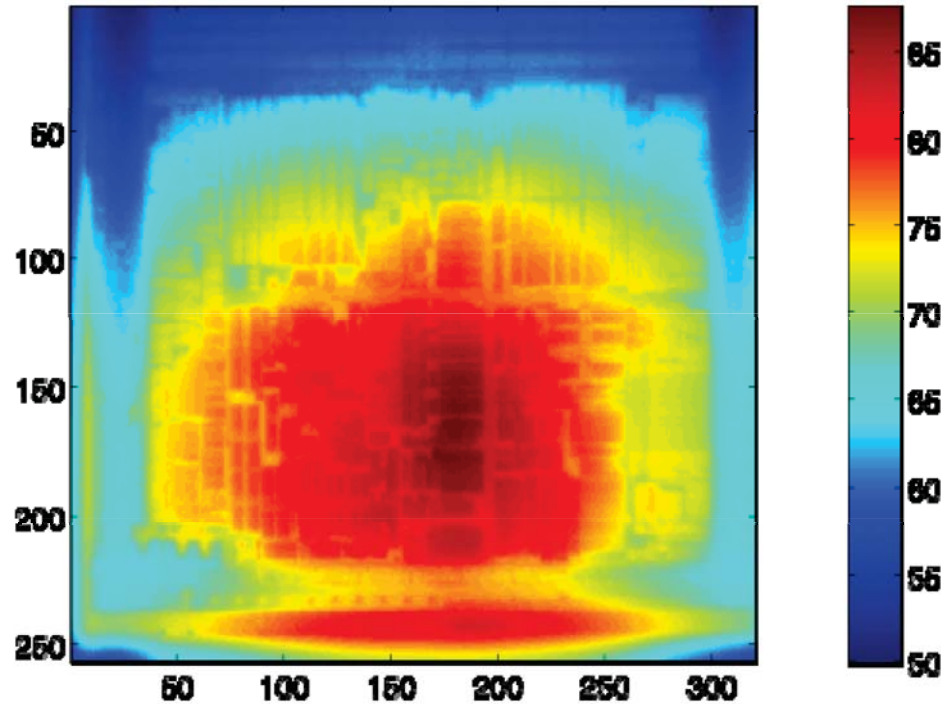


Liquid Crystal Thermography

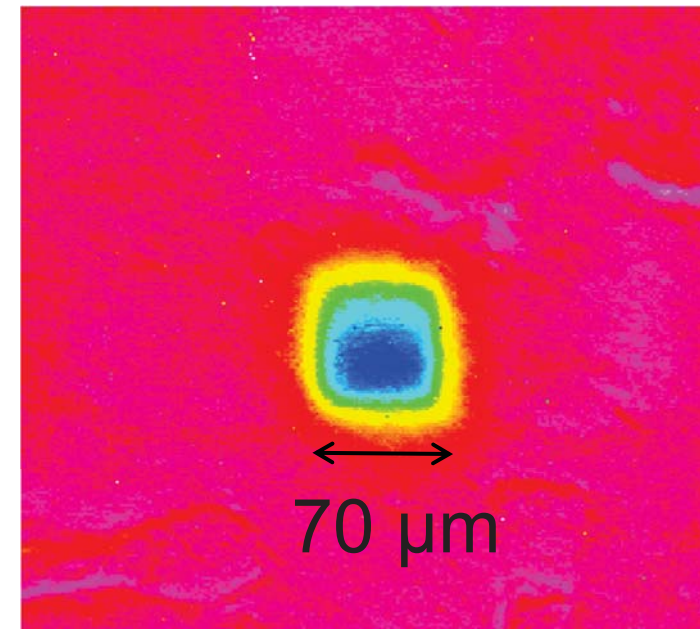


Calibrated infrared imaging

AMD Processor (cm)



Microrefrigerator



*Francisco Mesa-Martinez,
Jose Renau, UCSC*

<http://masc.cse.ucsc.edu>

Vivek Sahu, Georgia Tech

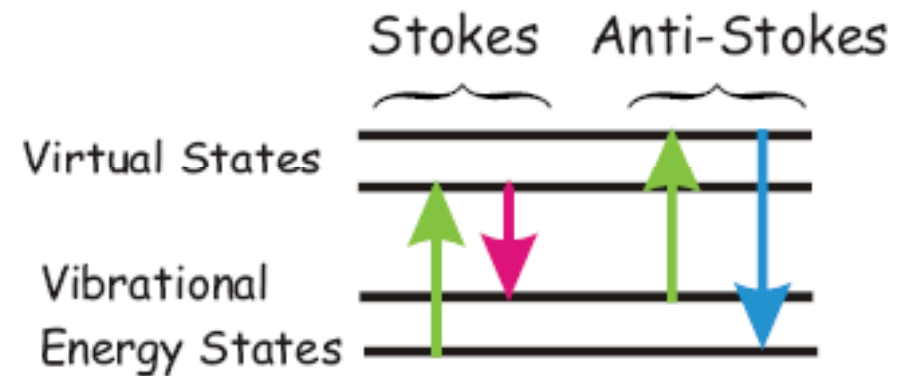
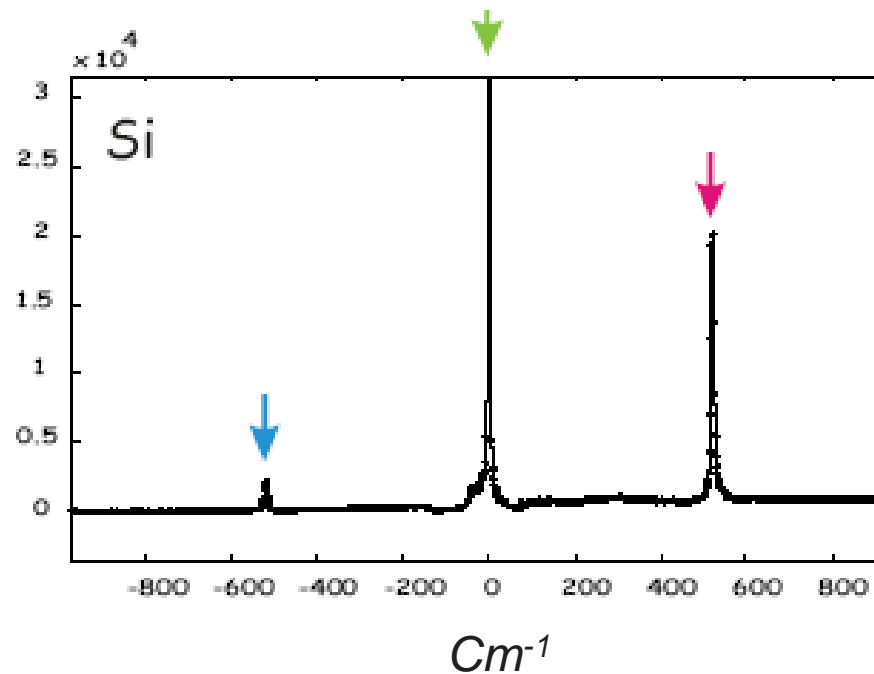


Method	Principle
Scanning thermal microscopy (SThM)	AFM with thermocouple or Pt thermistor tip
Optical Interferometry	Thermal Expansion, Michelson type
Micro Raman	Raman peak position and intensity is function of absolute T
Near Field Probe (NSOM)	Use near field to improve optical resolution



Raman spectroscopy and temperature measurement

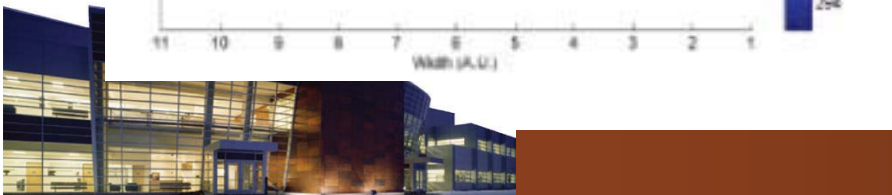
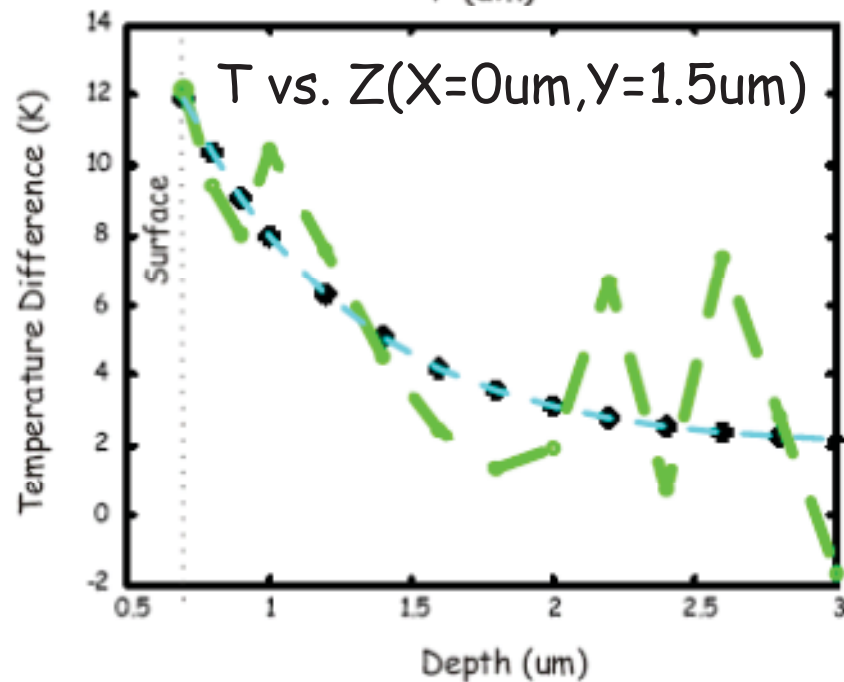
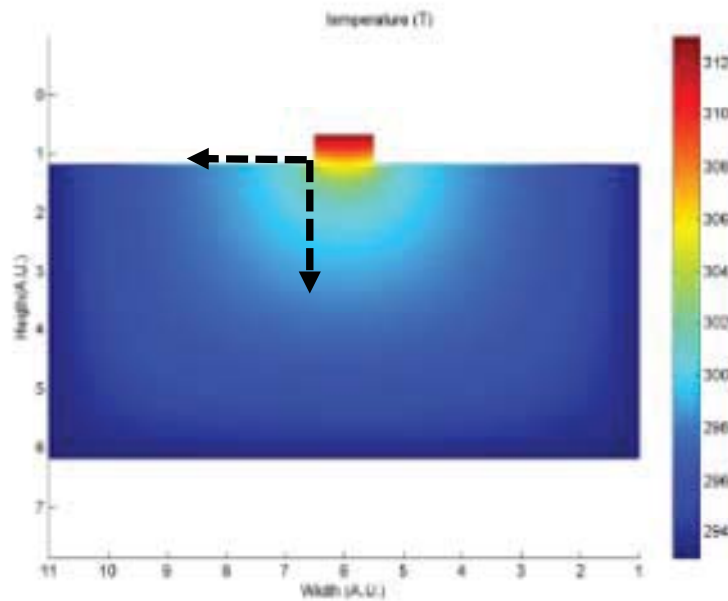
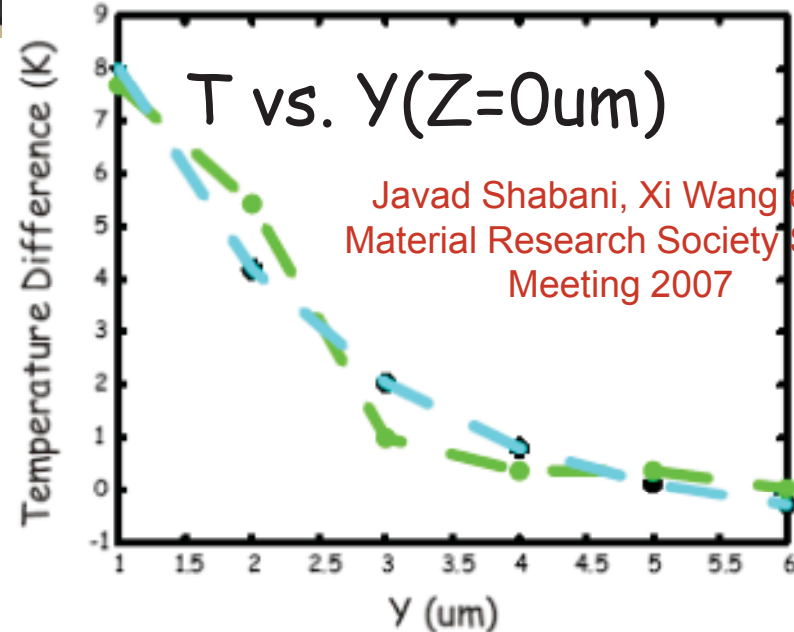
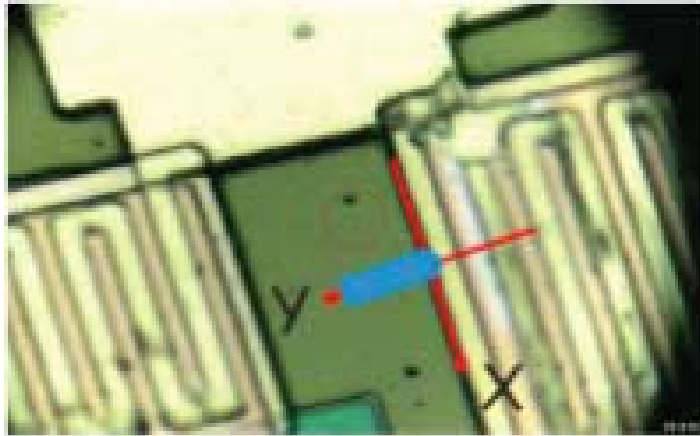
Scattered light intensity versus wavelength shift



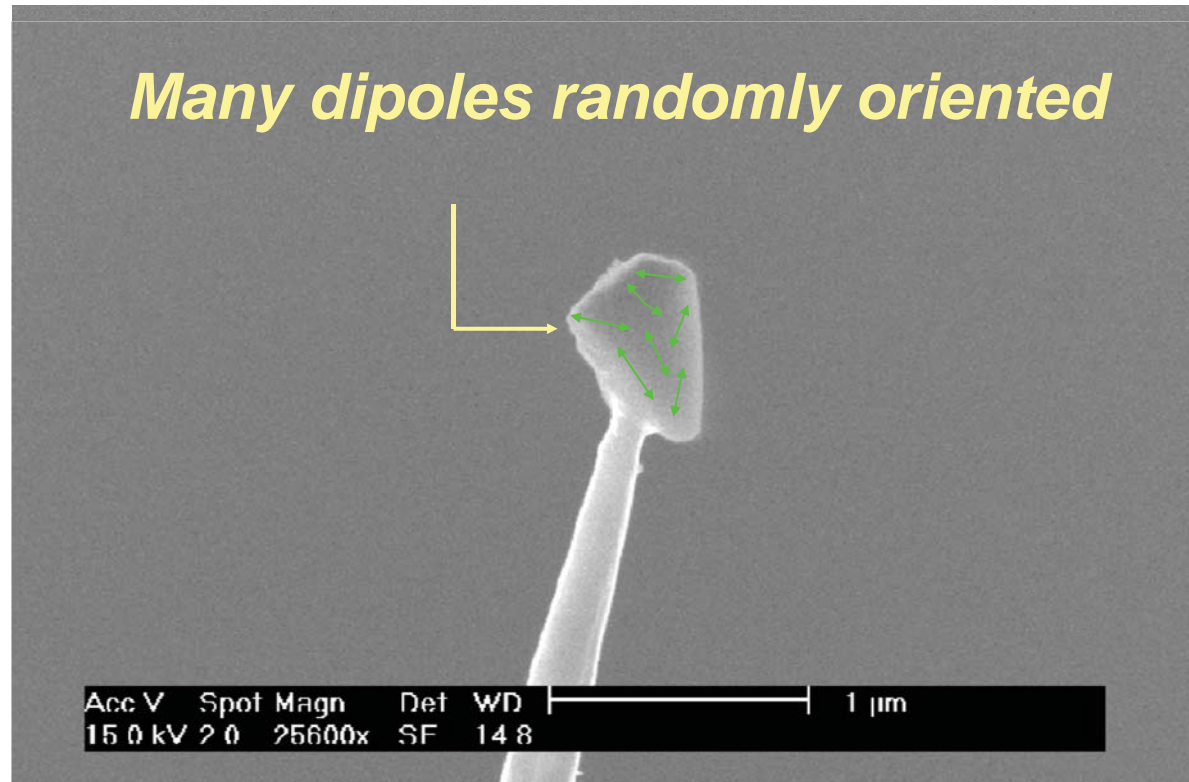
Needs laser illumination, high resolution spectrometer and a notch filter



3D Raman temperature measurement



Thermal imaging of nanostructures with a scanning fluorescent particle as a probe



Simplicity

APL, 83, 147 (2003)

**Infrared excitation :
emission and absorption lines well separated**

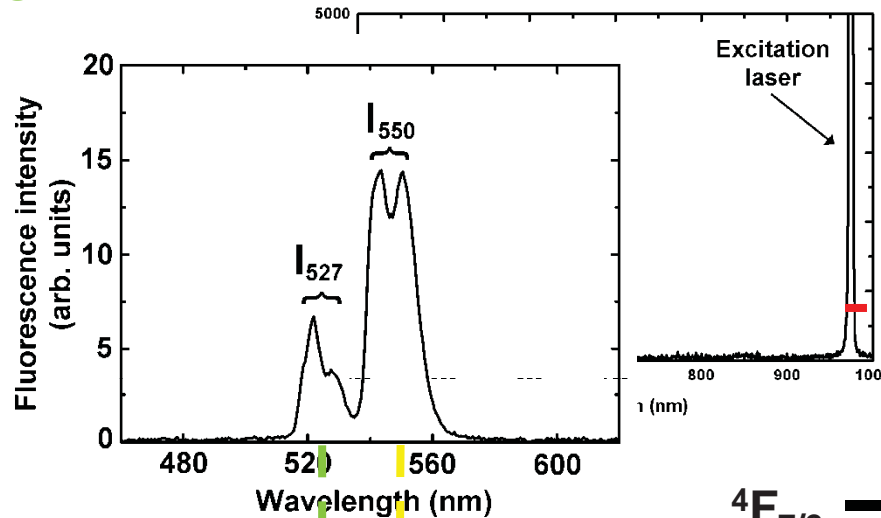


Lionel Aigouy, ESPCI, Paris, France

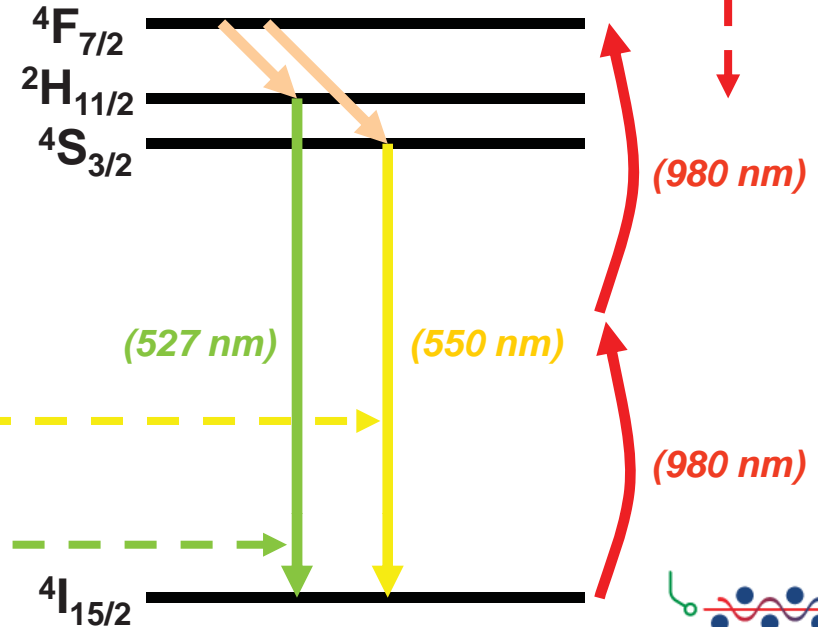
HOW CAN WE DEDUCE THE TEMPERATURE ?

Er / Yb ions

PL spectrum of Er / Yb doped particles



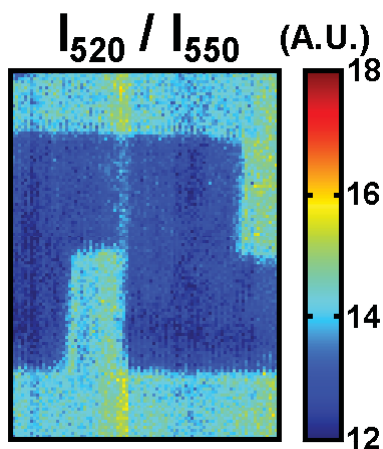
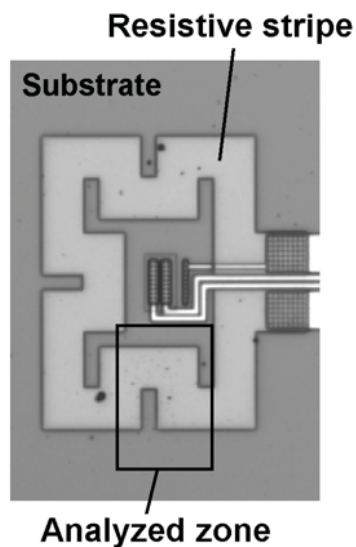
Lionel Aigouy, ESPCI,
Paris, France



$$\frac{I_{green}}{I_{yellow}} \propto \exp\left(-\frac{\Delta E}{k.T}\right)$$



Thermal imaging using Fluorescence Nanoparticles



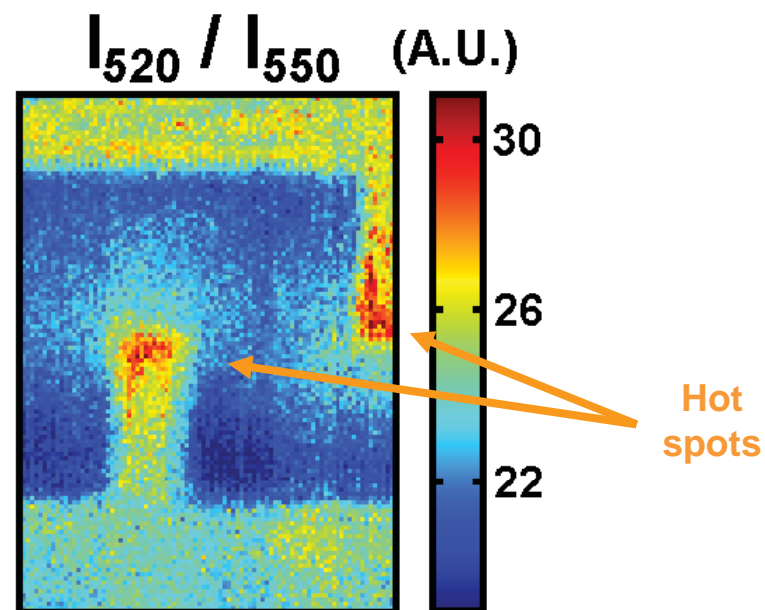
$I = 0$ mA
Uniform temperature
(room temperature)

Optical contrast visible
between different zones

Reference image

Lionel Aigouy, ESPCI, Paris, France

$I = 50$ mA

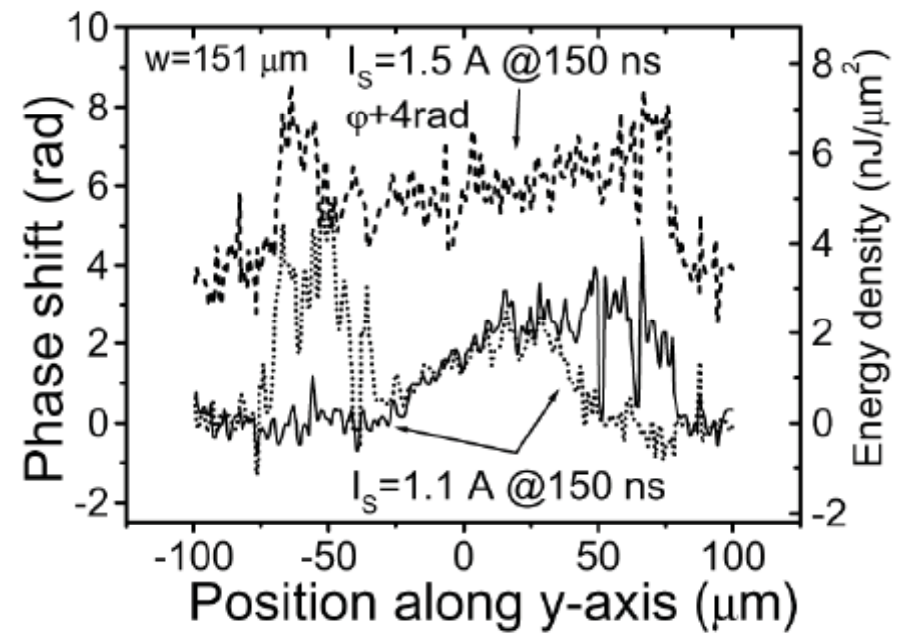
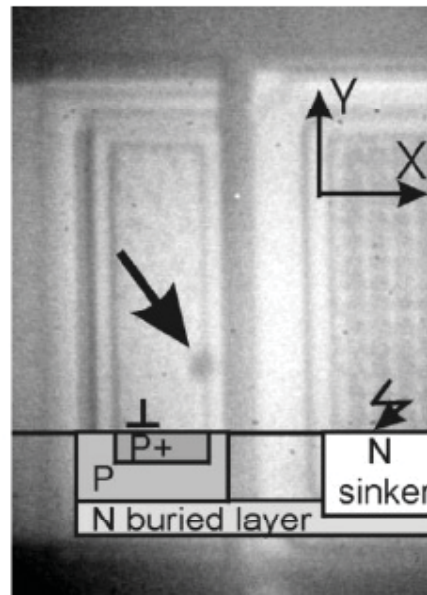
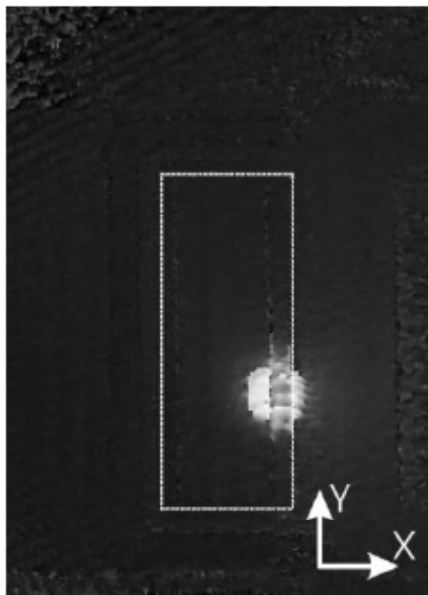
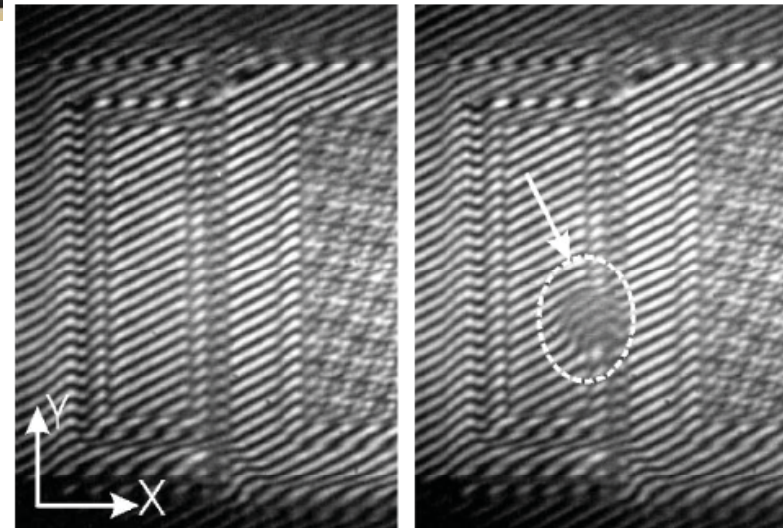


APL, 87, 184105 (2005).



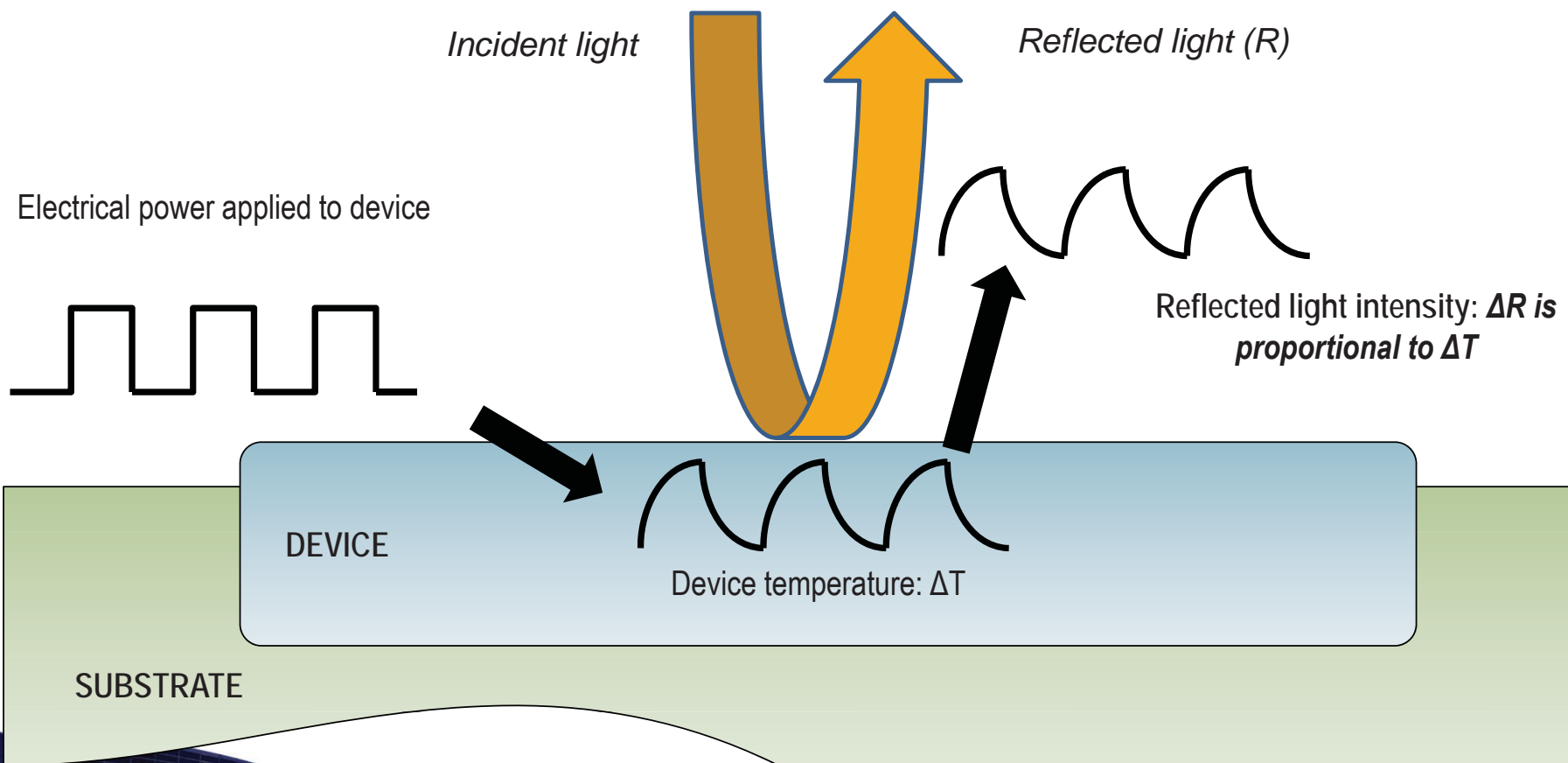
Interferometric measurements

Pogany, Gornik et al.,
TU Vienna 2003



Thermoreflectance Imaging

Optical reflectance changes with material temperature



J. Phys. D: Appl. Phys. **42** (2009) 143001

CCD-based thermoreflectance microscopy: principles and applications

M Farzaneh^{1,8}, K Maize², D Lüerßen^{3,4,9}, J A Summers³, P M Mayer^{4,10},
 P E Raad^{5,6}, K P Pipe⁷, A Shakouri², R J Ram⁴ and Janice A Hudgings³

$$\frac{\Delta R}{R} = \left(\frac{1}{R} \frac{\partial R}{\partial T} \right) \Delta T = \kappa \Delta T, \quad (1)$$

where κ , which is typically of the order of 10^{-2} – 10^{-5} K⁻¹,



The reflectivity R of the material for normal incidence of light has the form

$$R = \frac{(n - 1)^2 + k^2}{(n + 1)^2 + k^2}, \quad (3)$$

where n and k are the index of refraction and the extinction coefficient, respectively, and can be written as real and imaginary parts of the complex index of refraction $\hat{n} = n + ik$. Since Maxwell's equations yield the relation $\hat{\varepsilon} = \hat{n}^2$, it follows that

$$\varepsilon_1 = n^2 - k^2, \quad (4a)$$

$$\varepsilon_2 = 2nk. \quad (4b)$$



The optical constant ε_2 is related to the band structure through the joint density of states function [29]:

$$\varepsilon_2(E) = \frac{4e^2\hbar^2}{\pi\mu^2E^2} \int dk |P_{cv}(k)|^2 \delta[E_c(k) - E_v(k) - E], \quad (2)$$

where μ is the combined density of states mass, the Dirac δ function represents the joint spectral density of states between the conduction (c) and valence (v) band states which differ by the energy $E_c(k) - E_v(k) = \hbar\omega$ of the incident light, $P_{cv}(k)$ is the momentum matrix element between the conduction and valence band states, and the integration is performed over the first Brillouin zone.



the temperature increase causes a shift in the energy gap and broadens the critical point involved. Combining these two effects, one can write

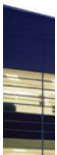
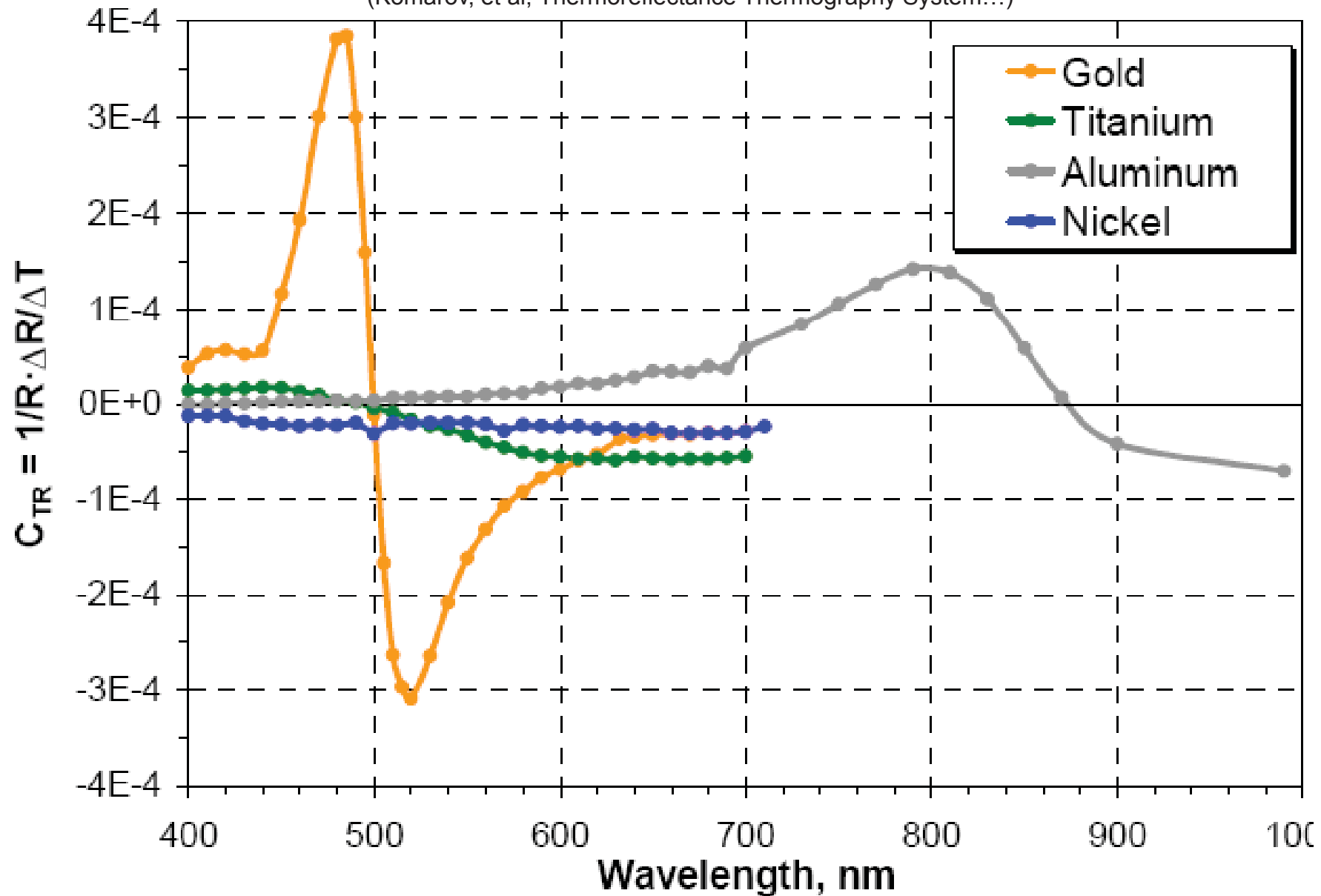
$$\Delta \hat{\varepsilon} = \frac{d\hat{\varepsilon}}{dE_g} \frac{dE_g}{dT} \Delta T + \frac{d\hat{\varepsilon}}{d\Gamma} \frac{d\Gamma}{dT} \Delta T, \quad (11)$$

where E_g is the energy gap and the broadening is accounted for, phenomenologically, by the broadening parameter Γ .



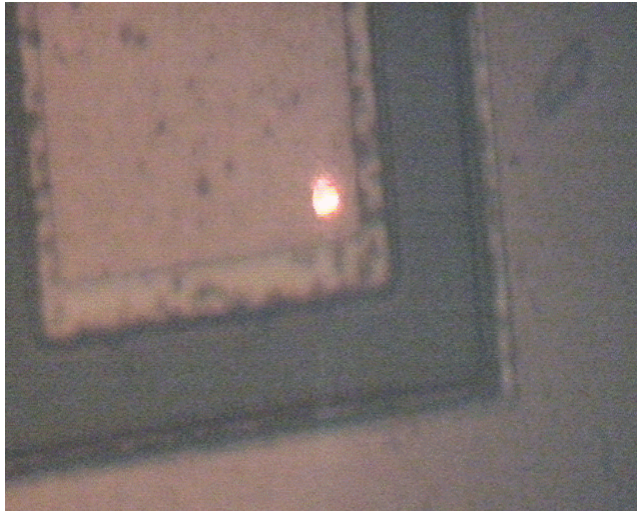
Thermoreflectance coefficient

(Komarov, et al, Thermoreflectance Thermography System...)

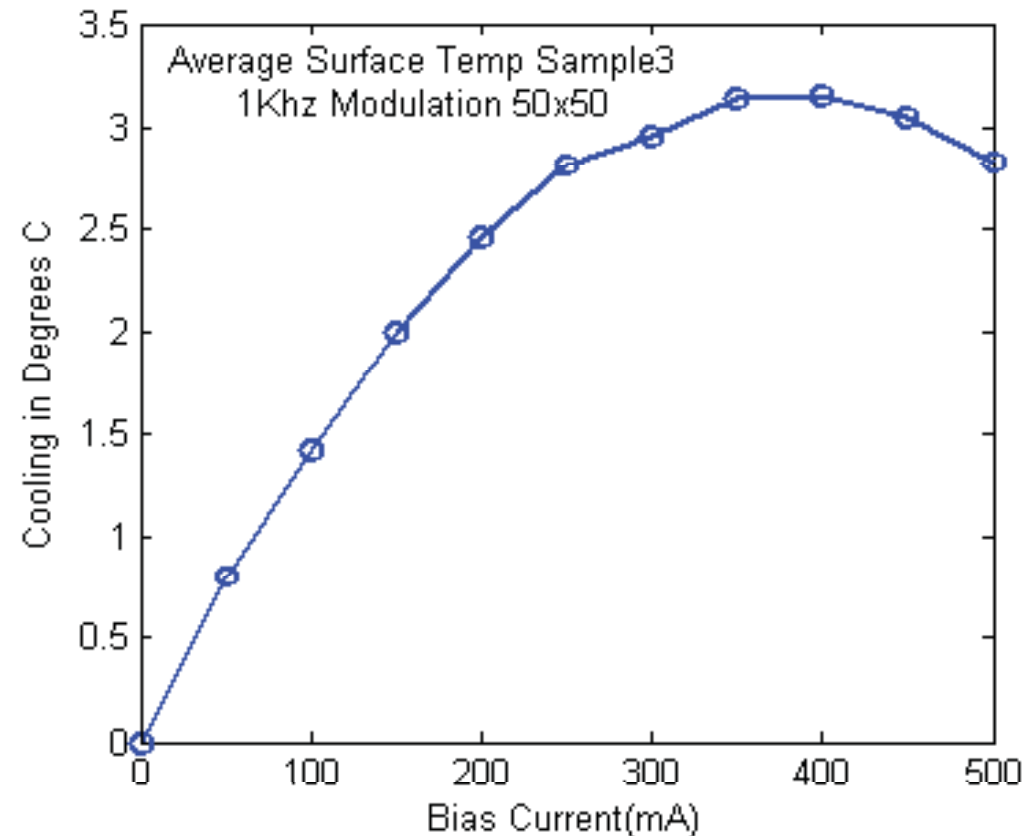


Laser measurement of localized temperature

J. Christofferson et al., SEMITHERM XVII , San Jose, Ca, March 2001.



Laser Probe on a micro cooler, lock-in detection at 1KHz



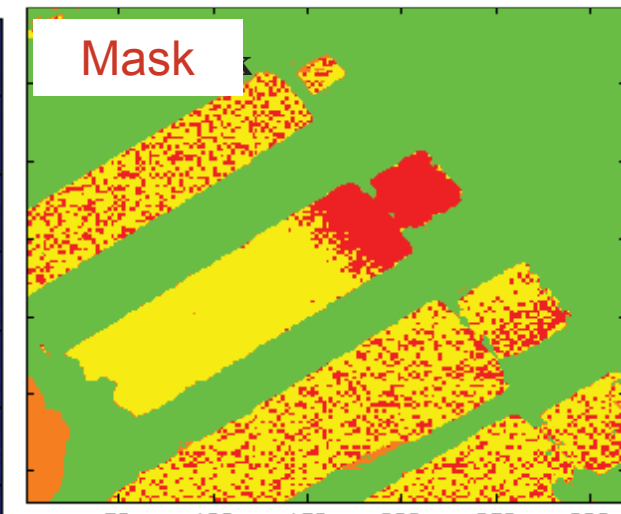
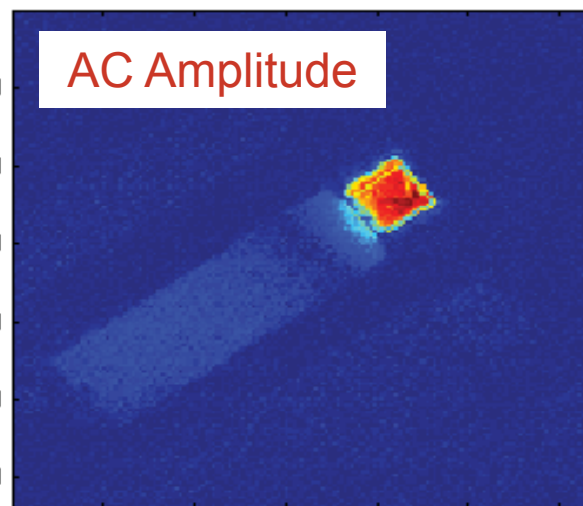
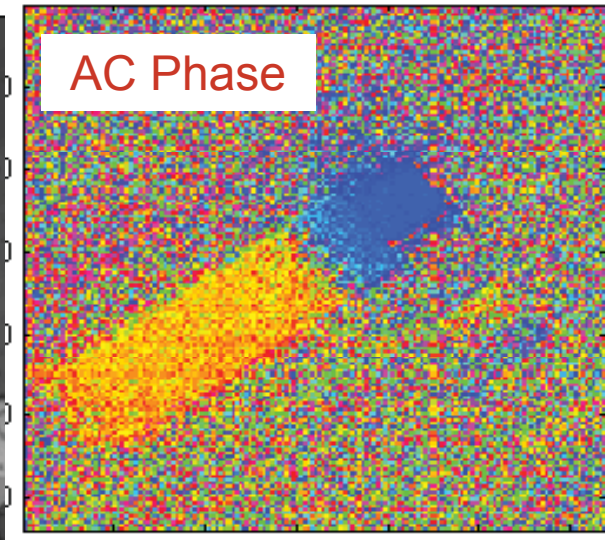
By modulating the device temperature, and by lock-in detection a small change in surface reflectivity due to temperature variation is detected.



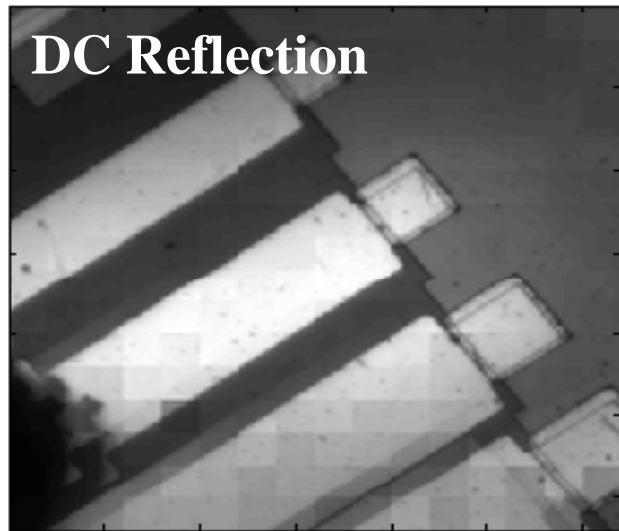
Lock-in imaging result

Acquisition time 5 minutes

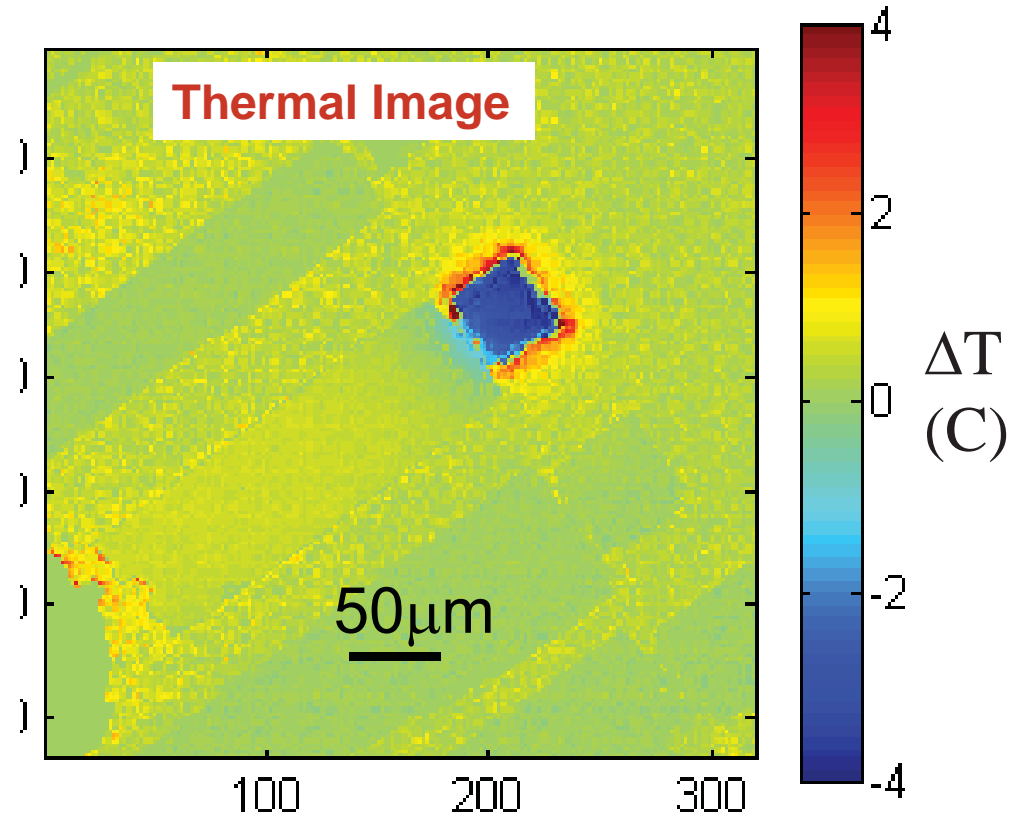
- DC Reflection
- AC Reflection
 - Phase
 - Amplitude
- Mask
 - Identify different materials, cooling/heating regions



Thermoreflectance image of microcooler



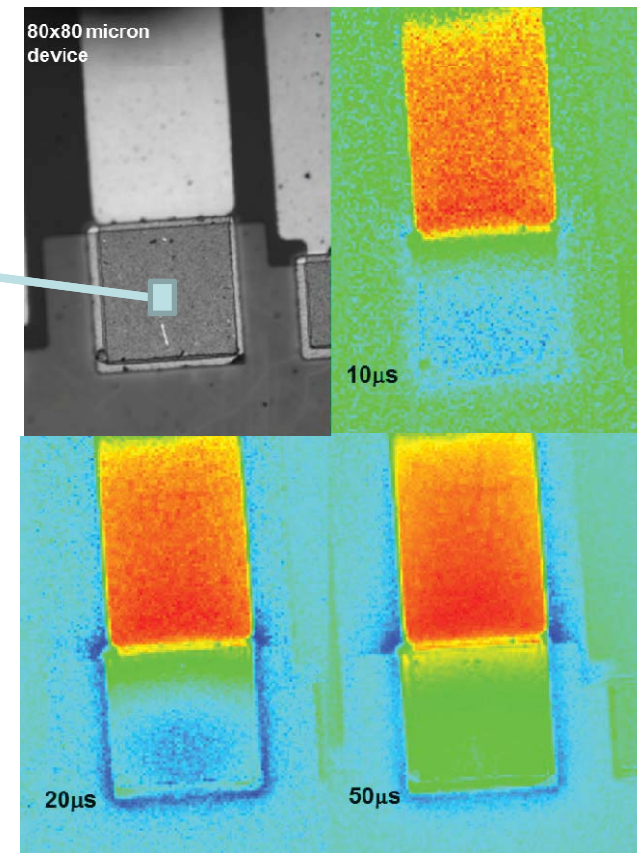
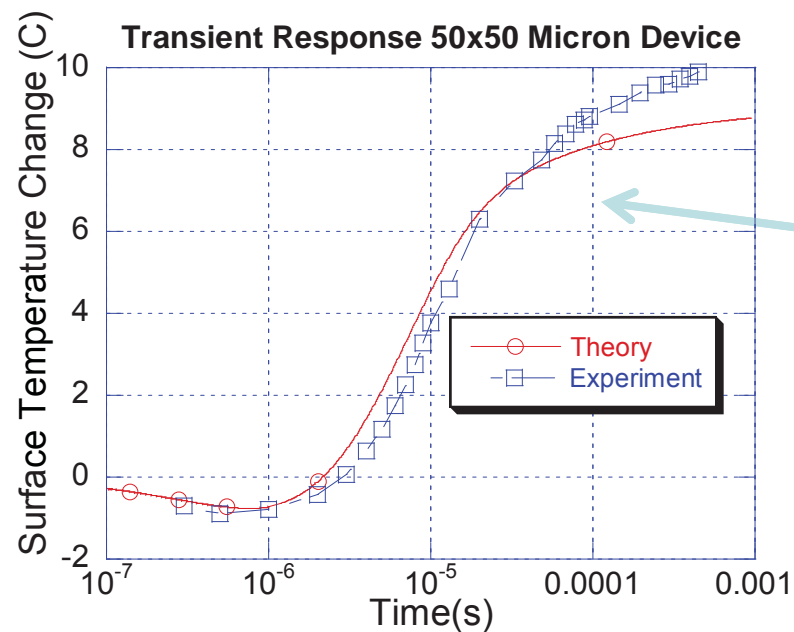
Pioneering works by:
Claeys, Fournier,
Dilhaire, Tessier,...



By modulating the device temperature, and by precise timing a small change in surface reflectivity due to temperature variation is detected.

Transient thermal images

Cooling Before Heating measured in
Overdriven micro cooler Semitherm 2009

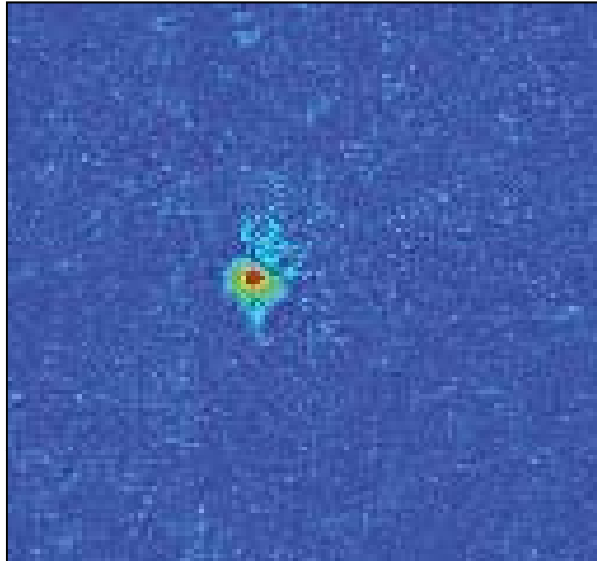
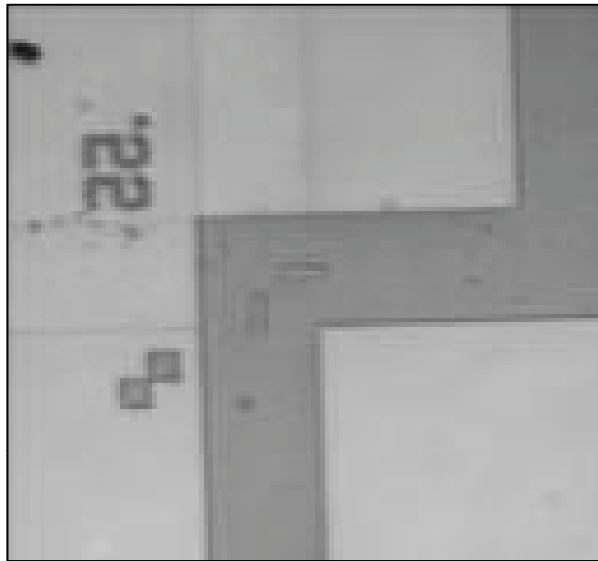


- **CCD based system:**
<http://www.microsanj.com>

Semitherm Conference
2009



Picosecond thermal imaging (800ps) *Discovery Park*

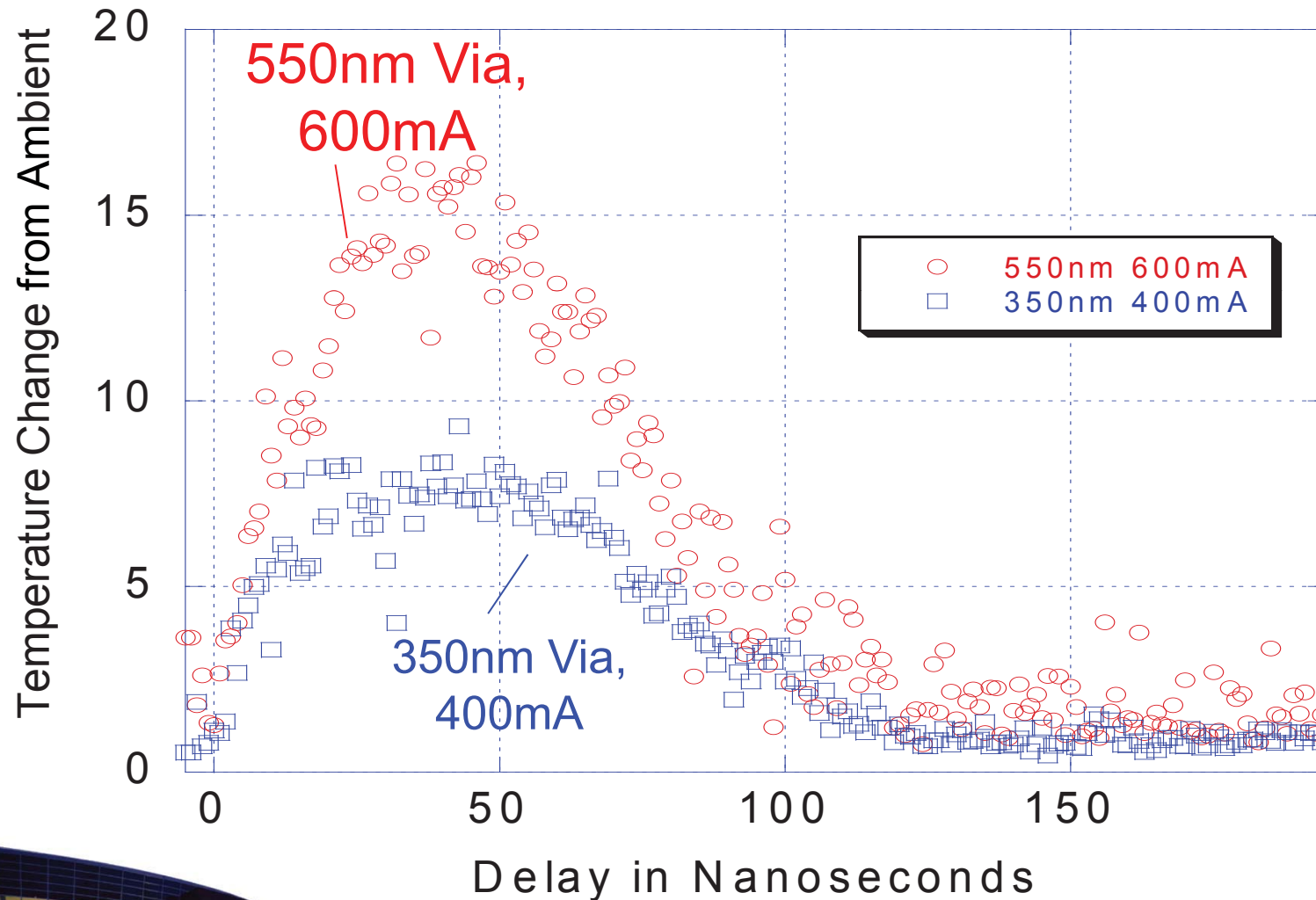


J. Christofferson et al., *Int. Heat Transfer Conf.*, August 2010



High Speed Thermal Imaging (800ps)

Study of heating in submicron interconnect vias



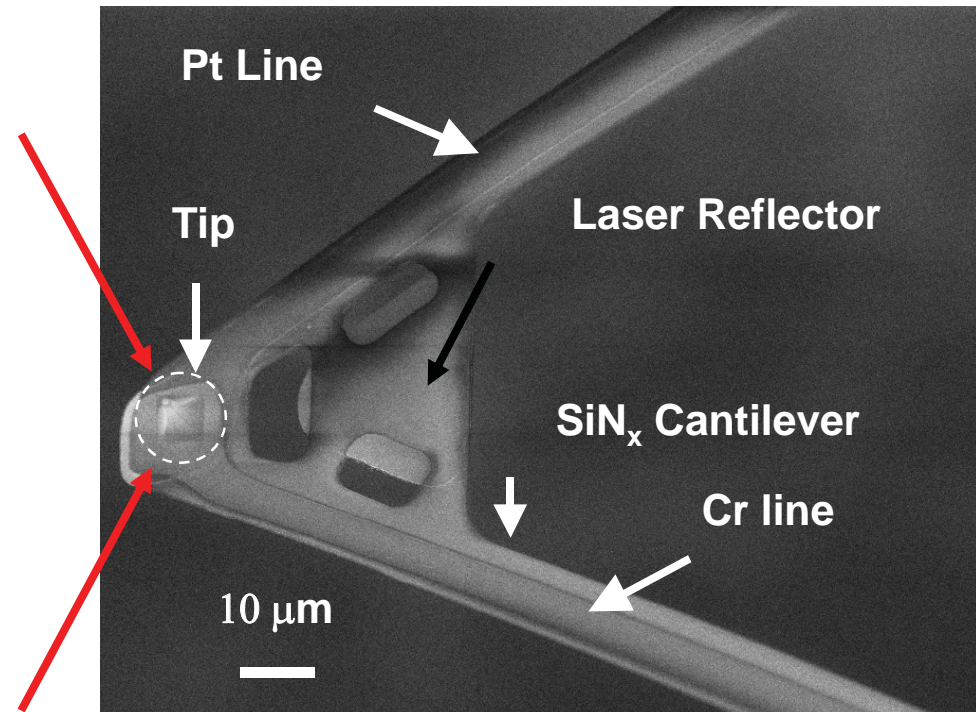
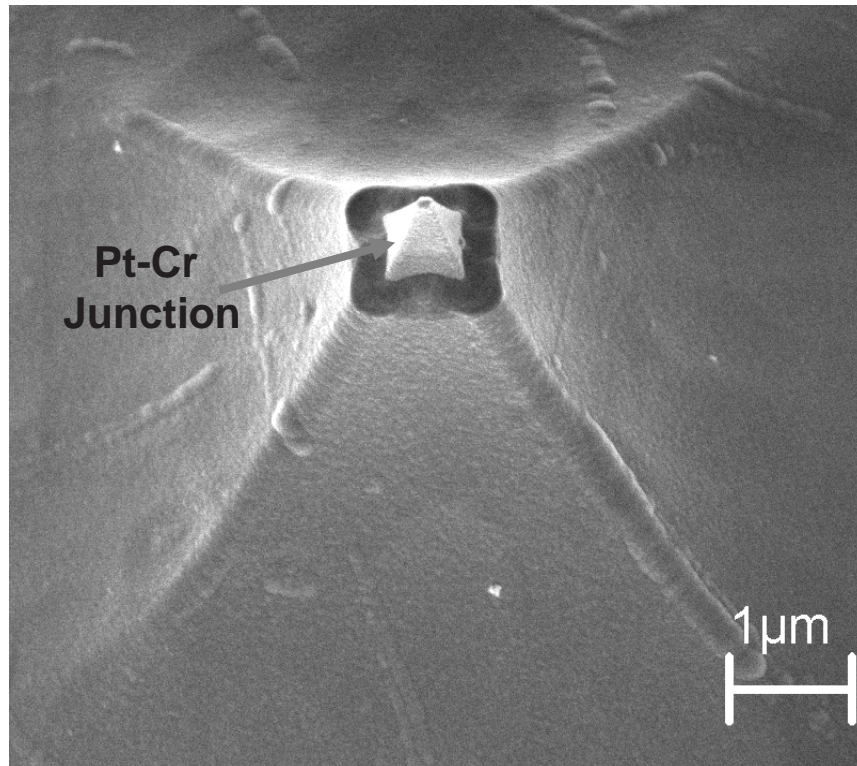
J. Christofferson et al., *Heat Transfer Conf.*, August 2010



J. Christofferson, et al, *J. Electronic Packaging*, 130 (4) 041101, 2008

Method	Resolution			Imag- ing?	Notes
	x(μ m)	T (K)	t(sec)		
μ thermocouple	50	0.01	0.1-10	No	Contact method
IR Thermography	3-10	0.02-1	1 μ	Yes	Emissivity dependent
Lockin IR Thermography	3-10	10 μ	NA	Yes	Need cycling
Liquid Crystal Thermography	2-5	0.5	100	Yes	Only near phase transition (aging issues)
Thermo-reflectance	0.3-0.5	0.08	800p-0.1 μ	Yes	Need cycling
Optical Interferometry	0.5	100 μ	6n-0.1 μ	Scan	Indirect measurement (expansion)
Micro Raman	0.5	1	10n	Scan	3D T-distribution
Near Field (NSOM)	0.05	0.1-1	0.1 μ	Scan	S/N dependent Tip/sample interaction
Scanning thermal microscopy (SThM)	0.05	0.1	10-100 μ	Scan	Contact method surface morphology





Cantilever Spring Constant: 0.1-1 N/m

Cantilever Deflection

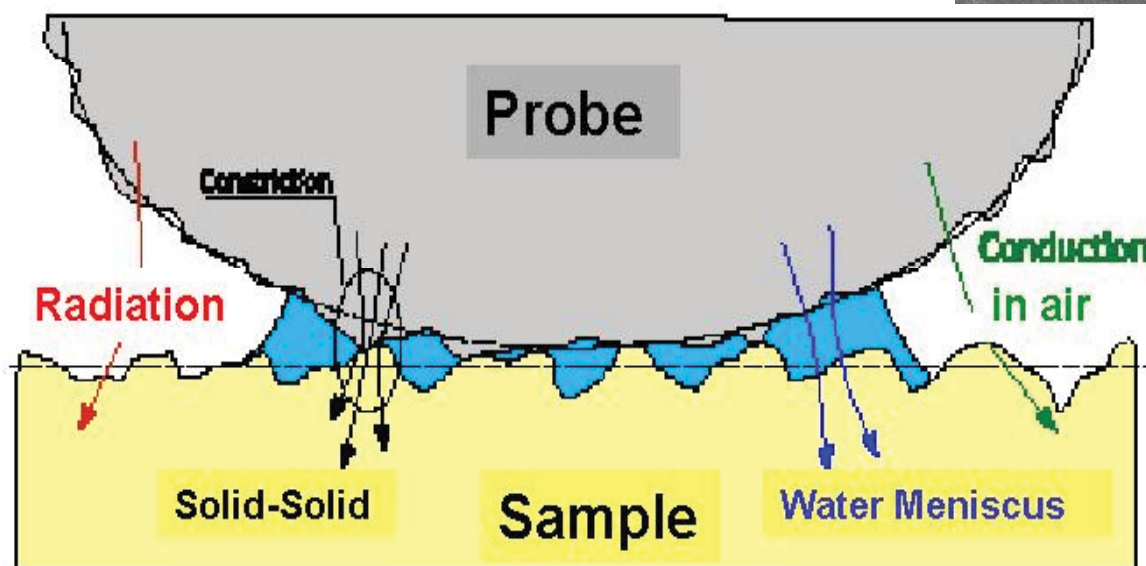
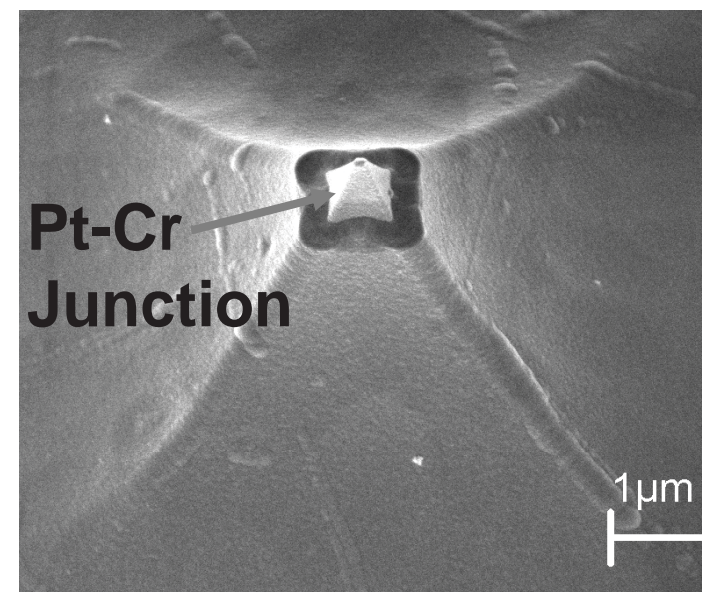
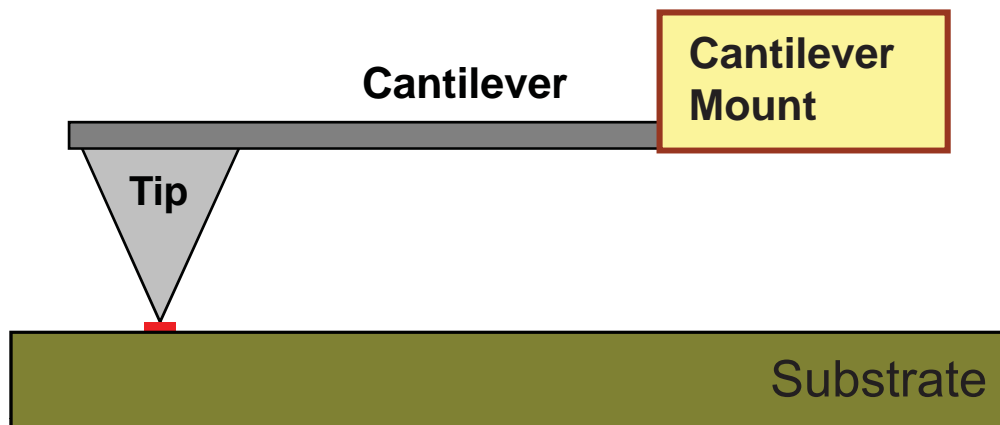
Detection Resolution: 0.01 nm

Force Resolution: 1-10 pN



Shi, Majumdar *et al.*, **J. MEMS**

Scanning Thermal Microscopy (SThM)



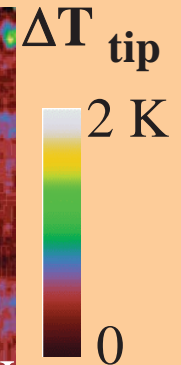
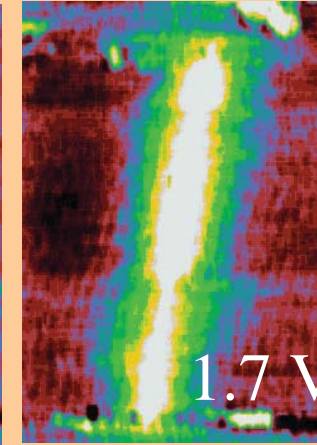
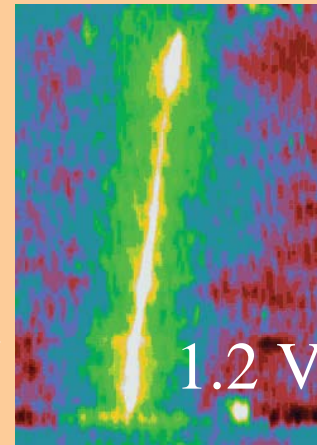
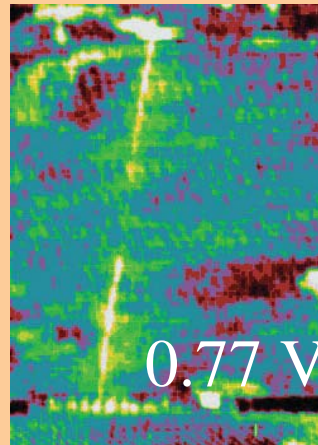
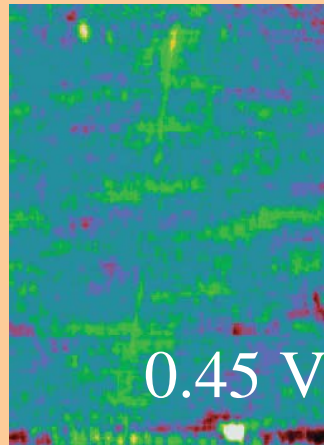
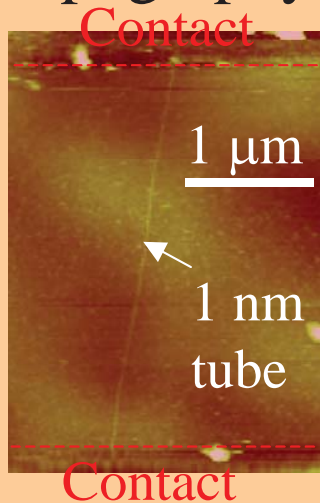
Courtesy: Arun Majumdar, UC Berkeley; Stefan Dilhaire, Univ. Bordeaux



SThM Metallic Single Wall Nanotube

Topography

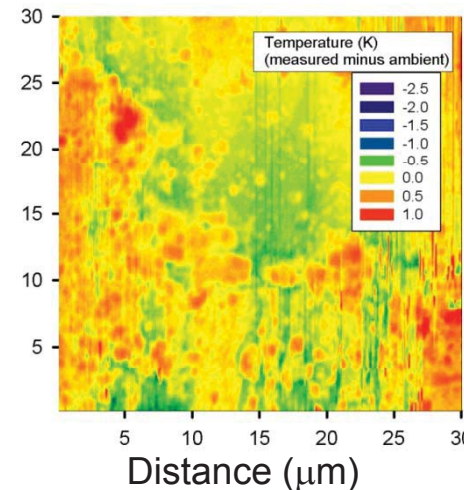
Thermal images



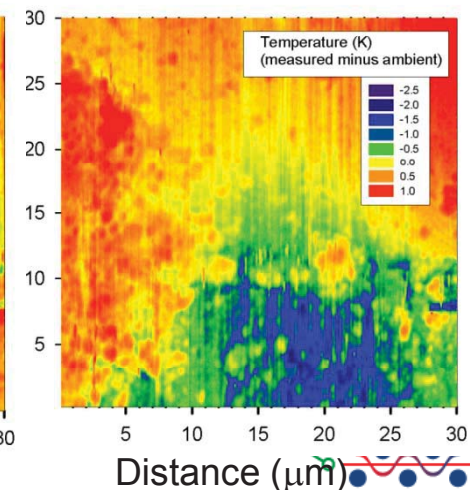
SThM Thermal Mapping of Microrefrigerators

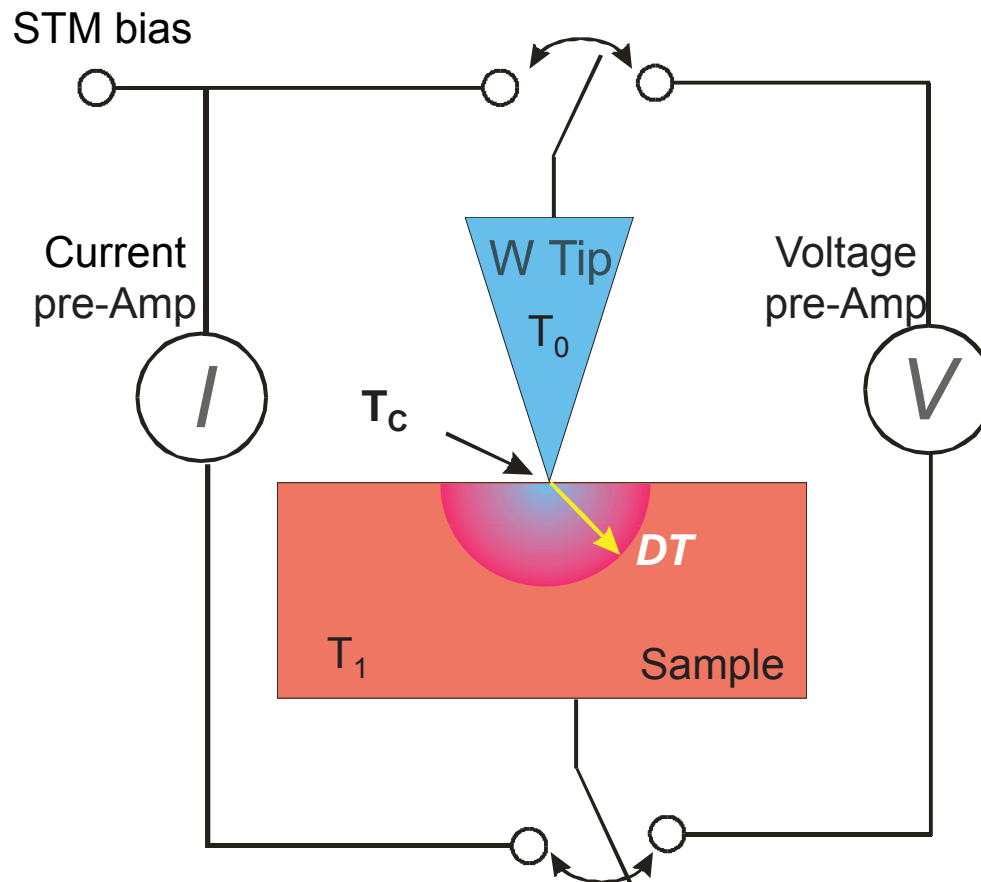
Prof. Arun Majumdar, UC Berkeley

Thermal, I=0



Thermal, I=200mA





- Elastic Nano-contact between metal tip and heated sample :

$$T_1 > T_c > T_0$$

- Local Temperature Gradient $\Delta T \equiv T_1 - T_c$

- Local Thermoelectric Voltage

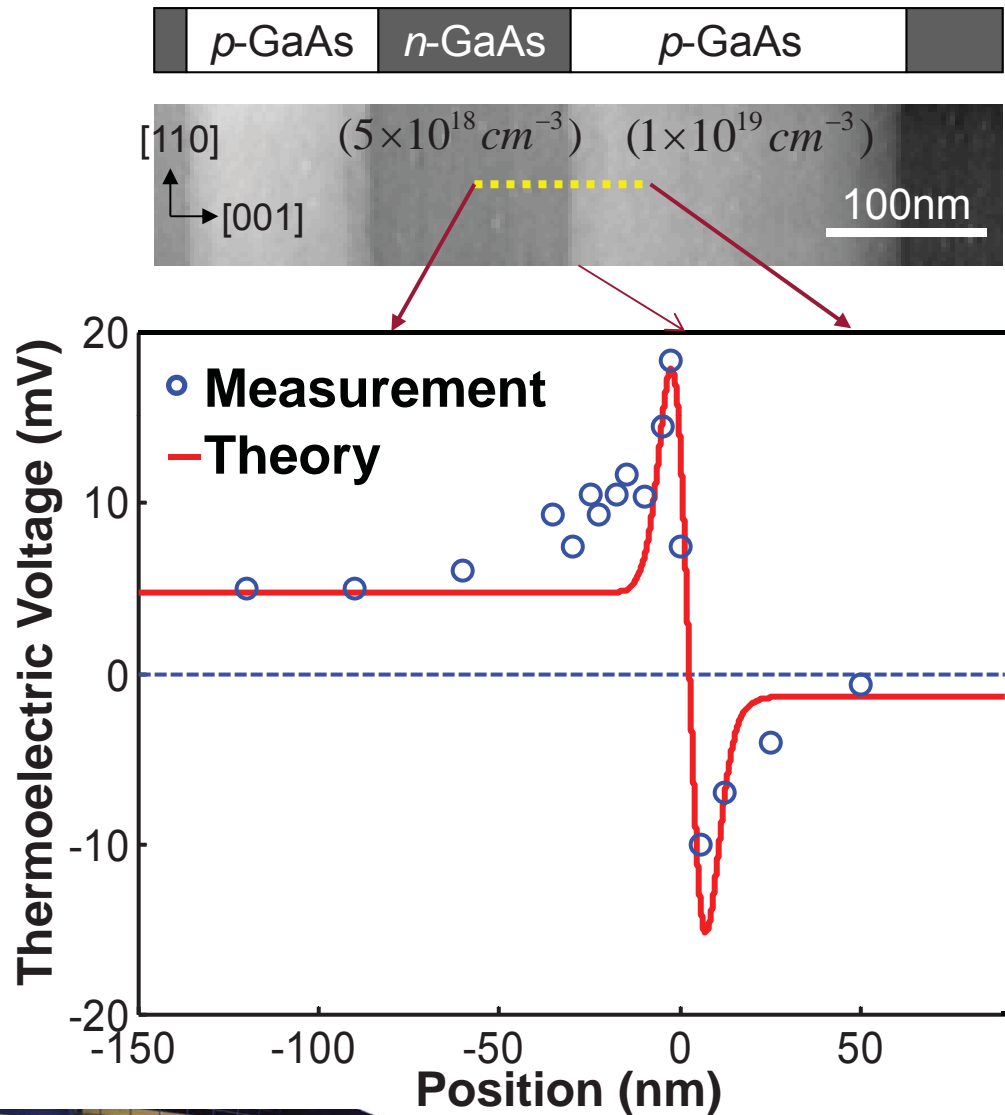
$$V = S(x, y)(T_1 - T_c)$$

- $V \rightarrow S$ profile

H.-K. Lyeo, L. Shi, and C.K. Shih.
(UT Austin)

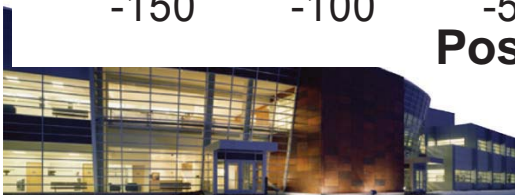


Mapping S of GaAs p - n Junction

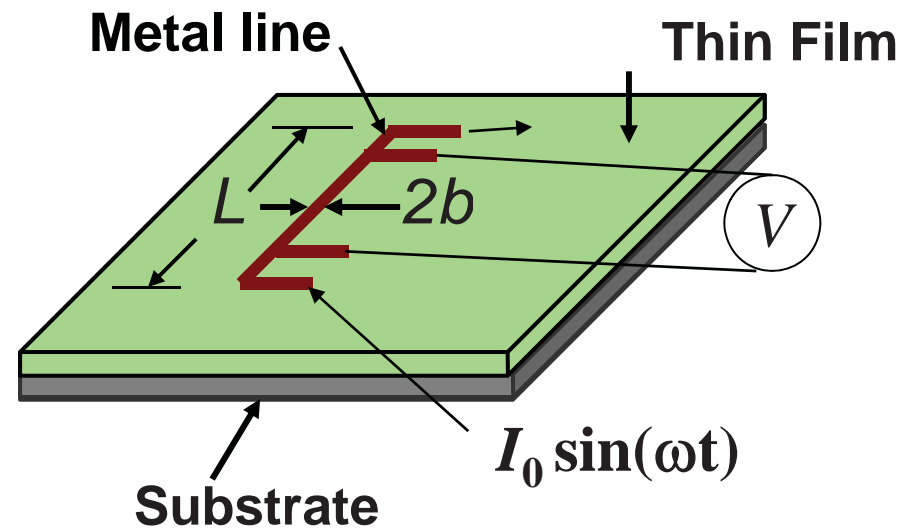


- Sharp transition across the junction
- Resolution of 6 nm
- Measure both carrier concentration and types

H.-K. Lyeo, A.A. Khajetoorians, L. Shi, K.P. Pipe, R.J. Ram, A. Shakouri, and C.K. Shih. *Science* **303**, 816 (2004)



3 ω method
(Cahill, *Rev. Sci. Instrum.* 61, 802)

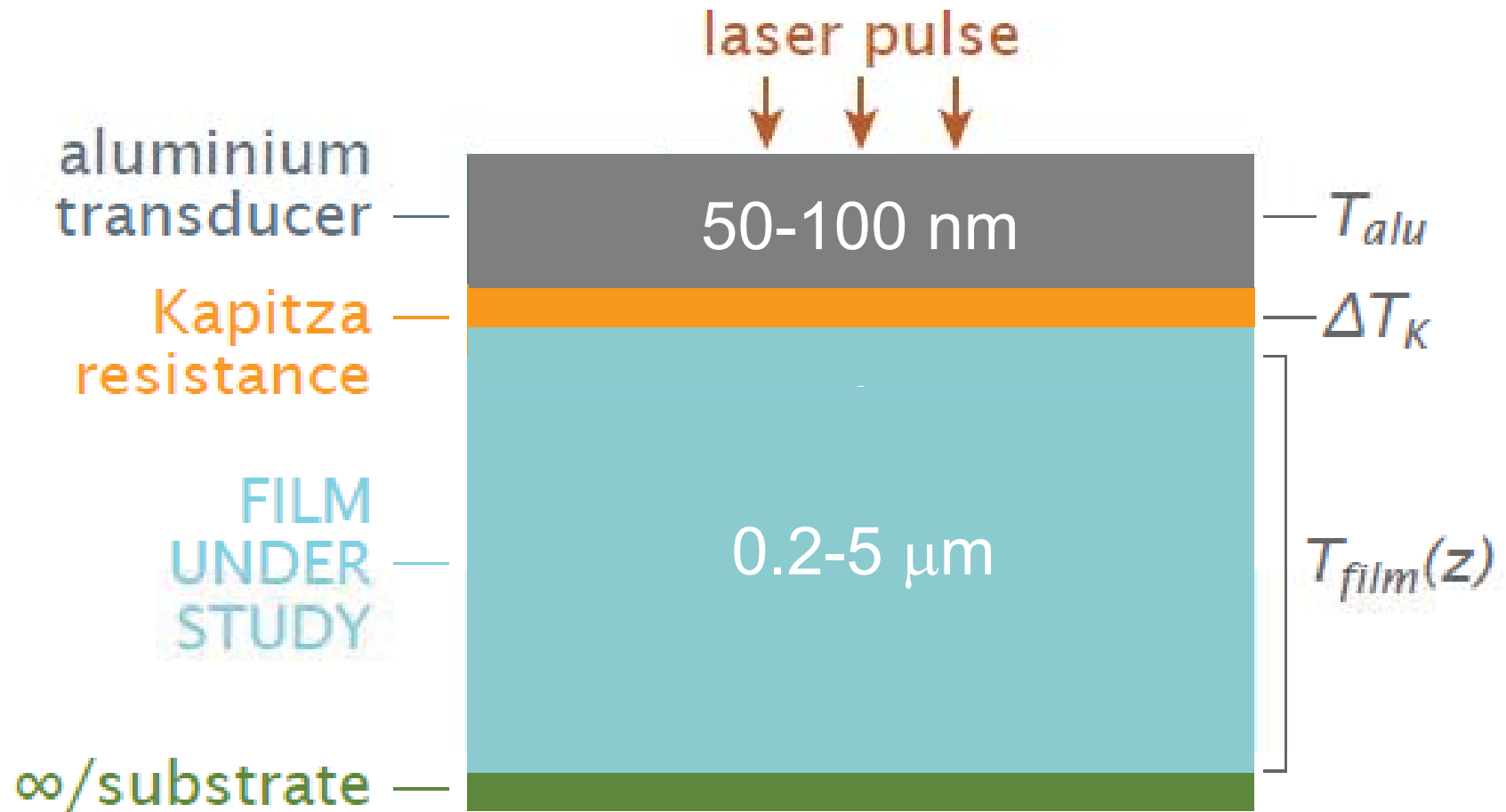


- $I \sim 1\omega$
- $T \sim I^2 \sim 2\omega$
- $R \sim T \sim 2\omega$
- $V \sim IR \sim 3\omega$

$$\Delta T(2\omega) = \frac{P}{L\pi k_s} \left[\frac{1}{2} \ln\left(\frac{D_s}{b^2}\right) + \eta - \frac{1}{2} \ln(2\omega) - \frac{i\pi}{4} \right] + \frac{Pd}{2Lbk_f}$$



Time Domain Thermoreflectance (TDTR)

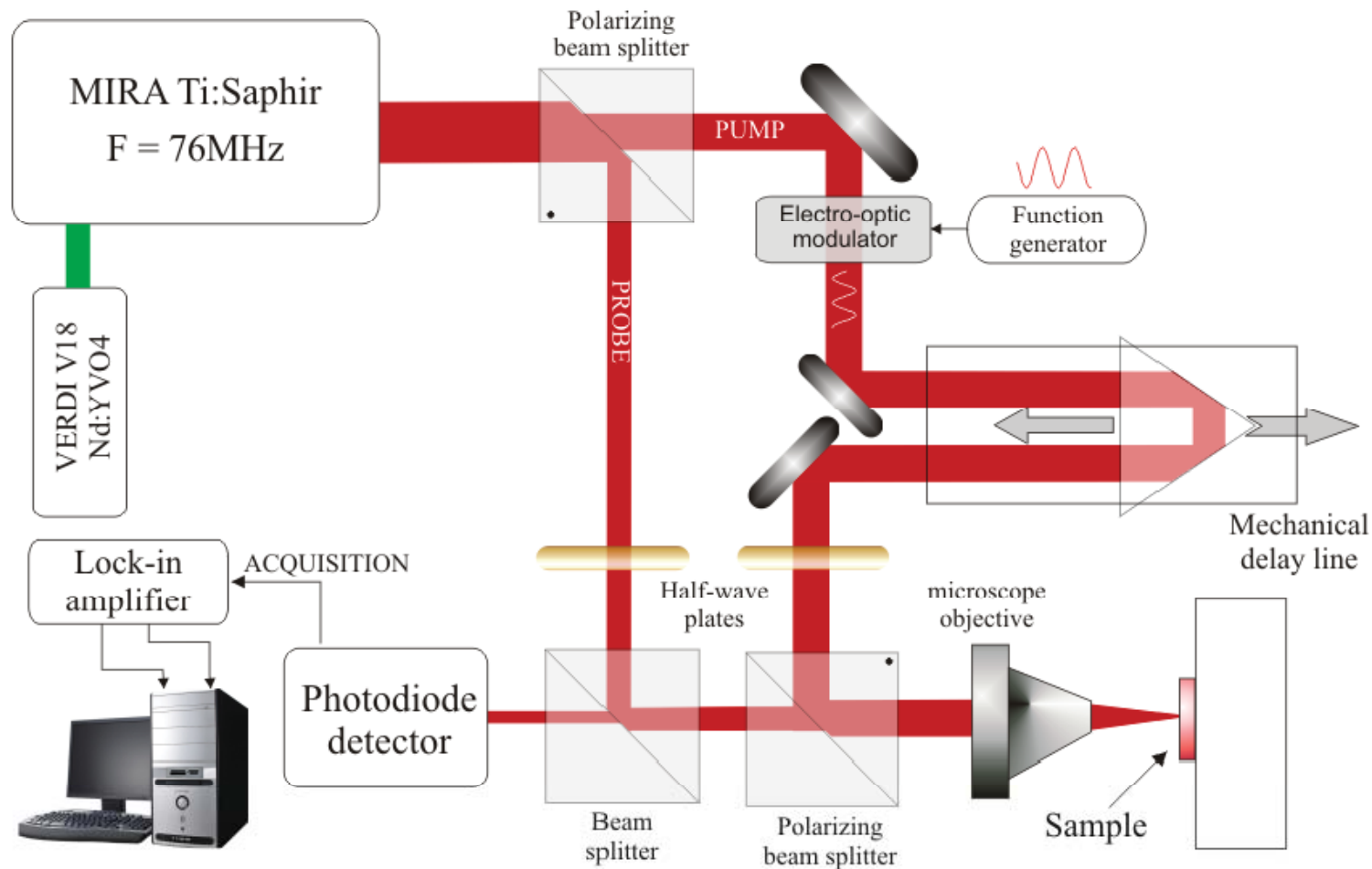


David Cahill, UIUC, 2003



Time Domain ThermoReflectance

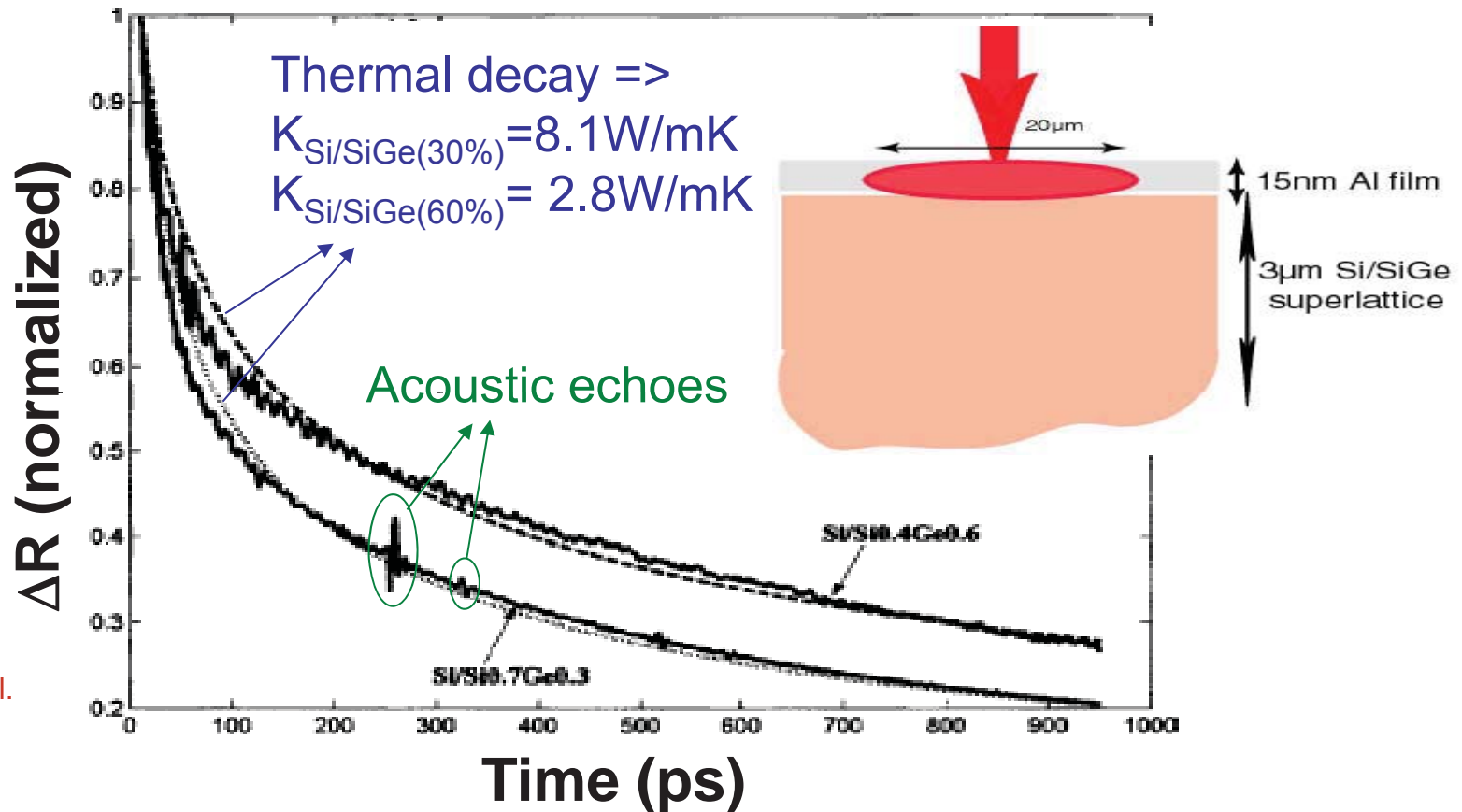
- **Modulated & delayed** femtosecond laser pulse used as a **Pump**.
- A **Probe** beam measures **reflectivity variation on the surface**
- The lock-in amplifier gives the **In-phase (V_{in})** and **Out-of-phase (V_{out})** signals.



Gilles Pernet (UCSC, Bordeaux)

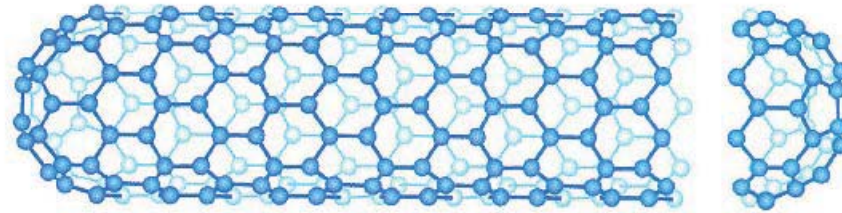


Thin Film Thermal Characterization



Y. Ezzahri et al. Appl.
Phys. Letters 2005

Metal film is heated by laser pulse and it acts both as a **heat source** and a **transducer** (creates acoustic waves). It can characterize thermal interface resistances as well as interface quality (acoustic mismatch).

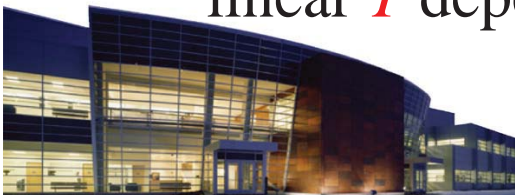


- Few scattering: long mean free path l

Strong SP^2 bonding: high sound velocity v

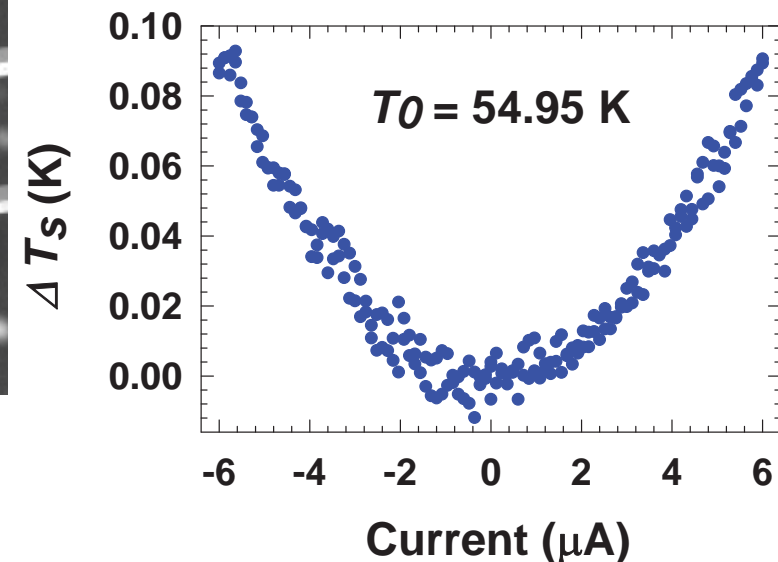
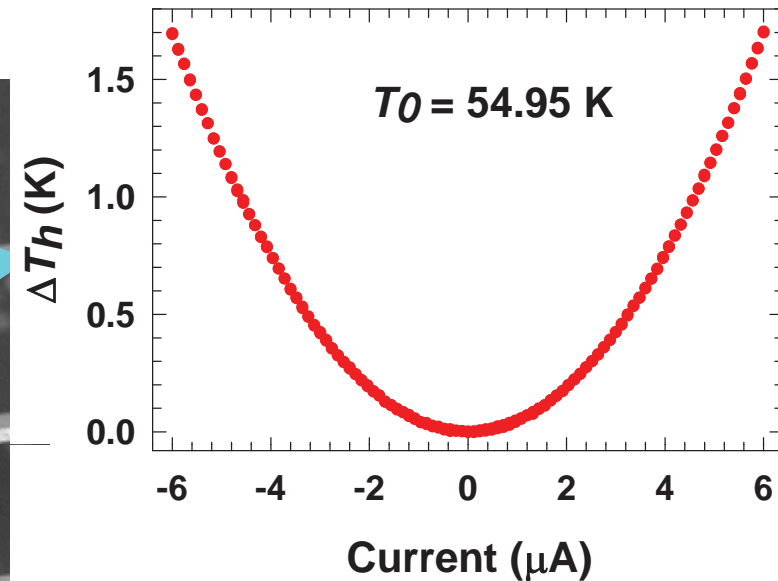
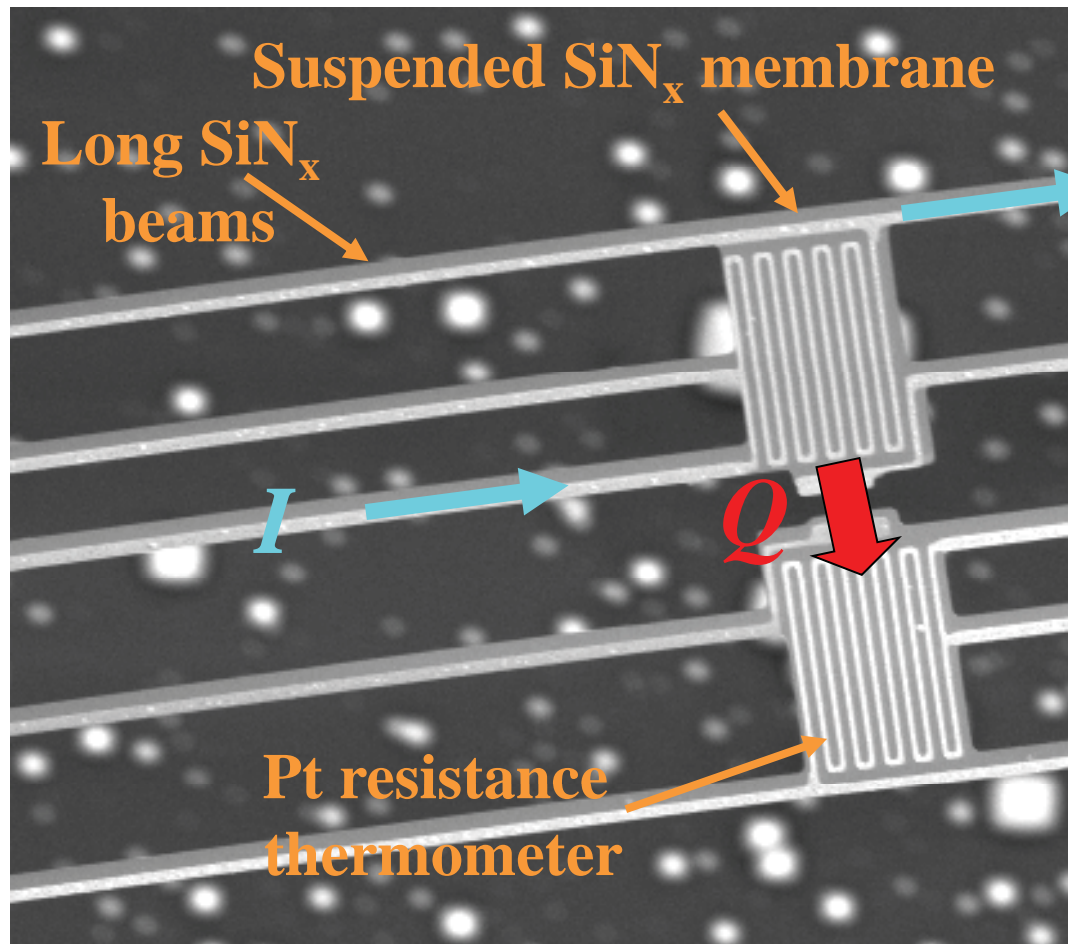
→ high thermal conductivity: $k = Cvl/3 \sim 6000$ W/m-K

- Below 30 K, thermal conductance → $4G_0 = (4 \times 10^{-12}T)$ W/m-K,
linear T dependence (G_0 : Quantum of thermal conductance)



Thermal Measurements of Nanowires

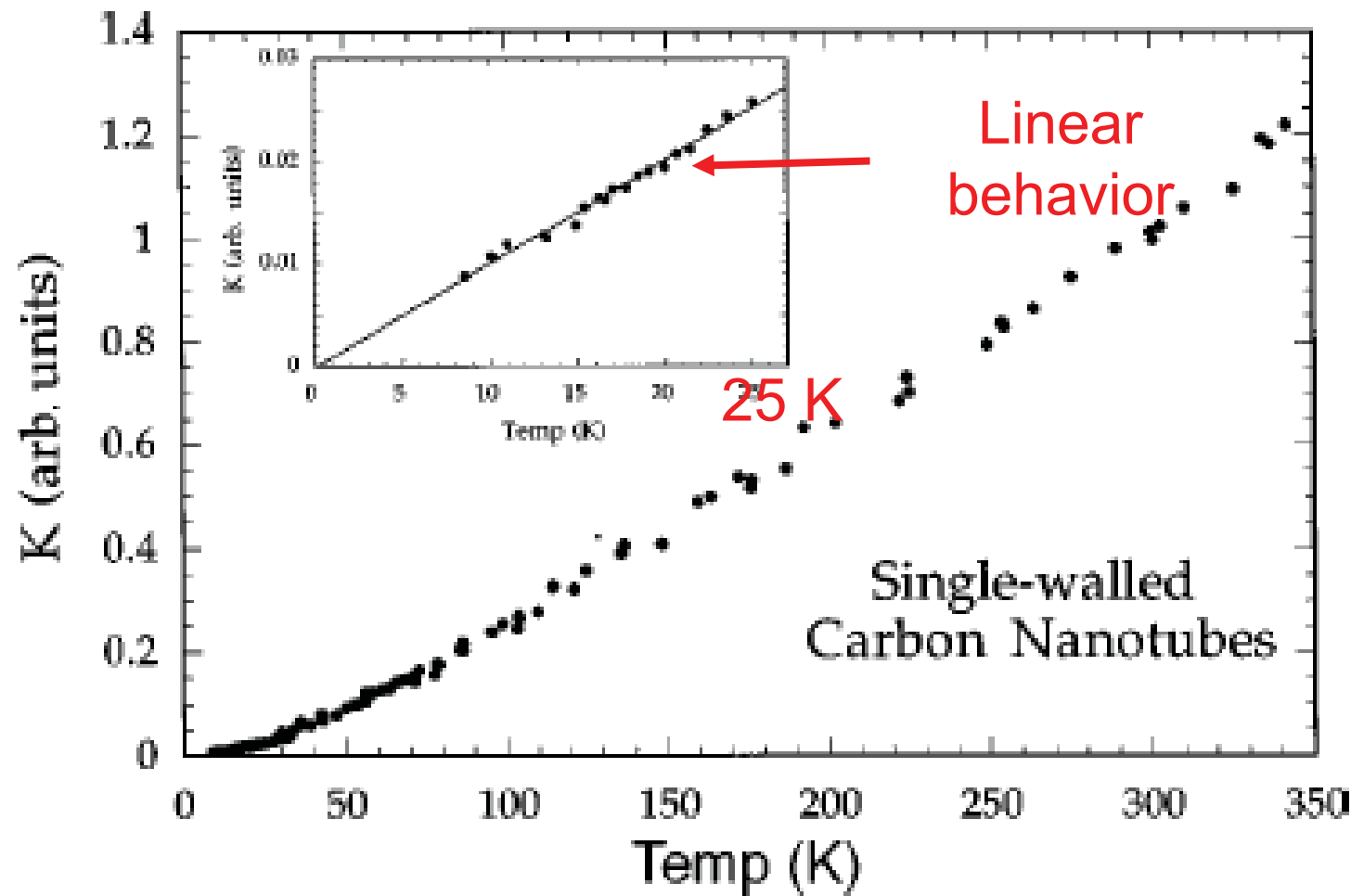
Thermal conductance: $G = Q / (T_h - T_s)$



Kim et al, *PRL* 87, 215502
Shi et al, *JHT*



Thermal Conductance of a Nanotube

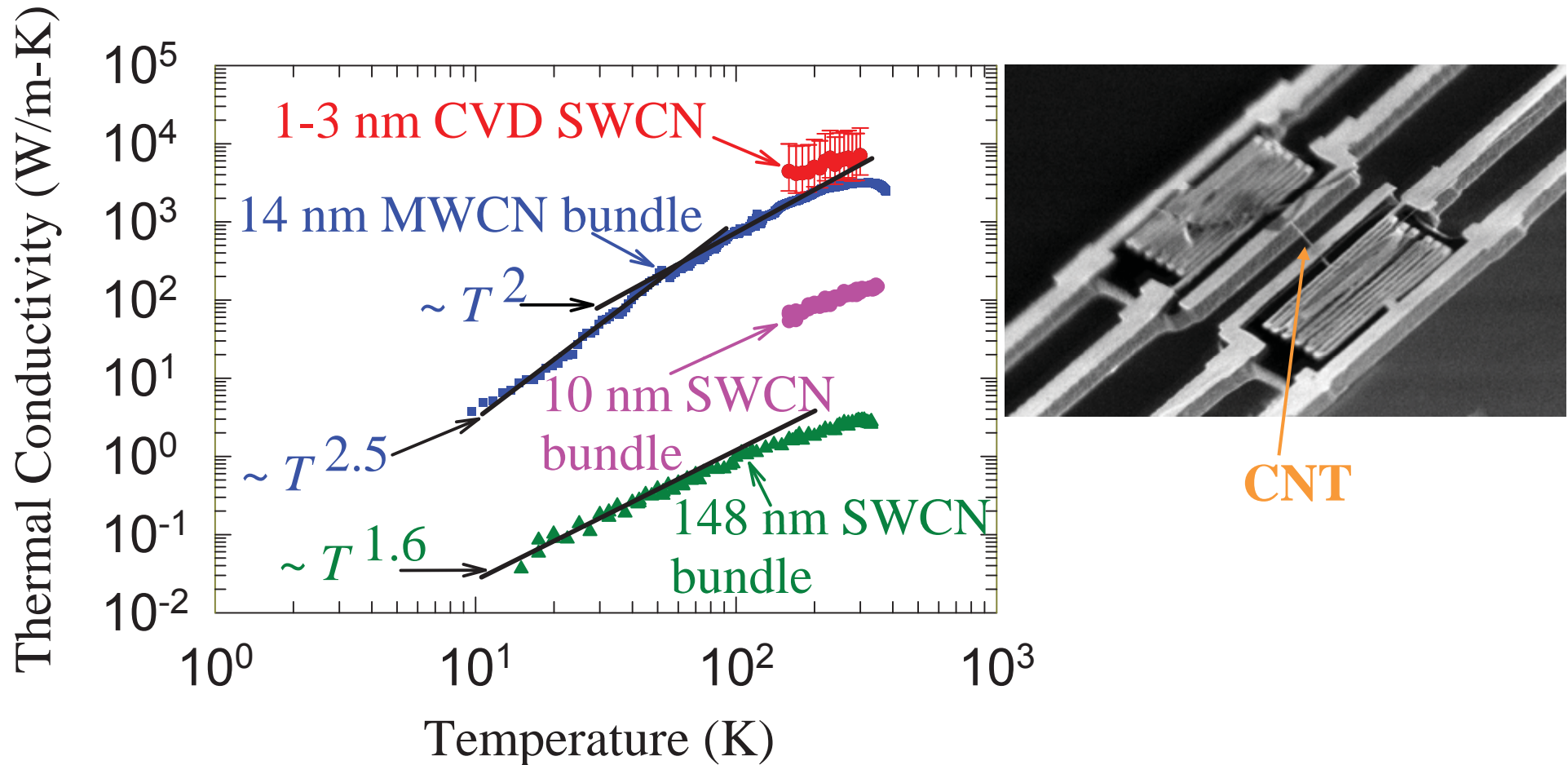


Ref: Hone et al.
APL 77, 666

- Estimated thermal conductivity at 300K: $\sim 250 \ll 6000$ W/m-K
→ Junction resistance is dominant
- Intrinsic property remains unknown



Thermal Conductivity of Carbon Nanotubes



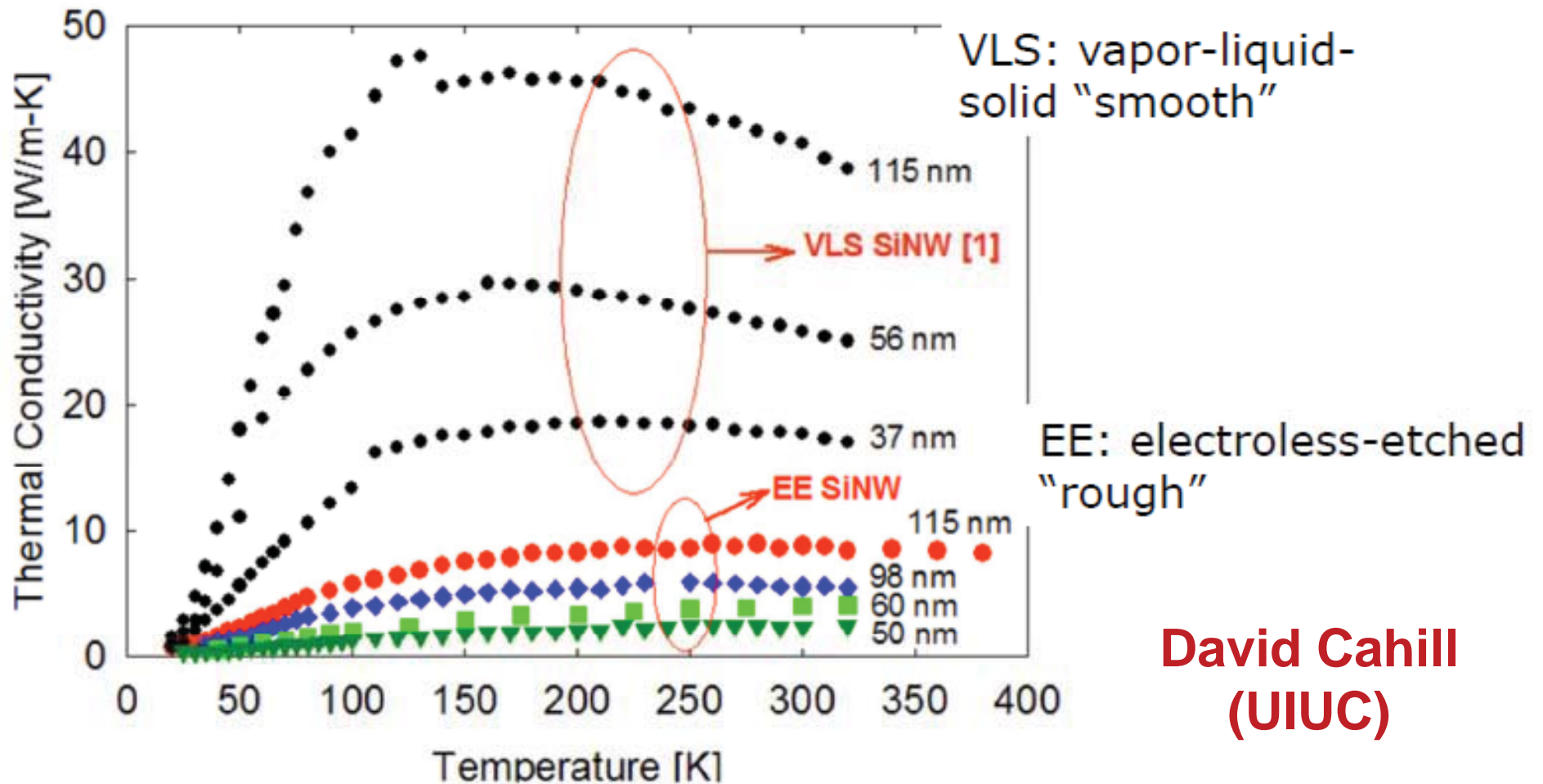
- An individual nanotube has a high $k \sim 2000-11000$ W/m-K at 300 K



Li Shi, UT Austin

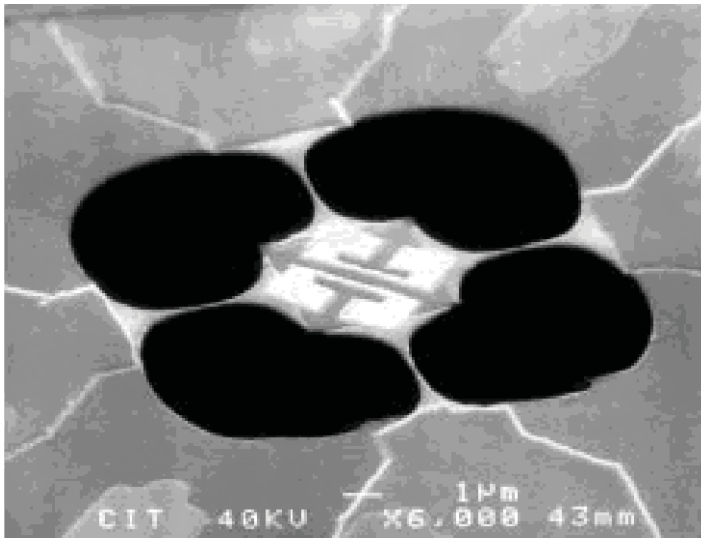
New phonon physics in roughened nanowires?

Single Si nanowire measurements by Majumdar, Yang, and co-workers (2008)

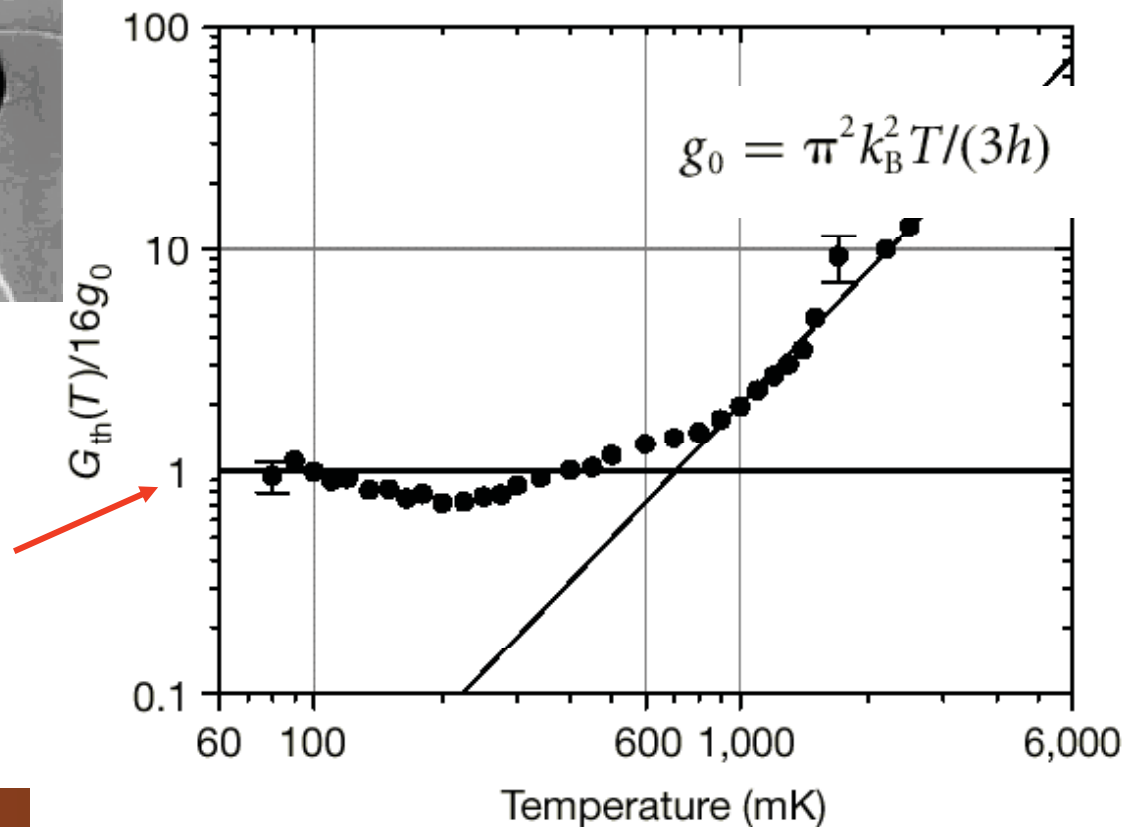


David Cahill
(UIUC)

Thermal conductance quantization in nanoscale SiN_x beams
(Schwab *et al.*, *Nature* 404, 974)



Quantum of Thermal
Conductance



Summary (Part I)

- Thermal characterization techniques
 - Suspended MEMS heaters
 - 3ω
 - Scanning thermal and thermoelectric microscopy
 - Time Domain Thermo Reflectance (TDTR)
 - Raman spectroscopy
- Ultra high thermal conductivity (CNT, graphene)
- Thermoreflectance imaging

Nanoscale heat transport and microrefrigerators on a chip;
A. Shakouri, Proceedings of IEEE, July 2006

**J. Christofferson, et al, *J. Electronic Packaging*, 130 (4)
041101, 2008**

100µm

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